



## Table of Contents

<b>1 特性</b> .....	1	9.4 Device Functional Modes.....	28
<b>2 应用</b> .....	1	<b>10 Application and Implementation</b> .....	32
<b>3 说明</b> .....	1	10.1 Application Information.....	32
<b>4 Revision History</b> .....	2	10.2 Typical Application.....	32
<b>5 说明 (续)</b> .....	3	10.3 System Example.....	35
<b>6 Device Comparison Table</b> .....	3	<b>11 Power Supply Recommendations</b> .....	36
<b>7 Pin Configuration and Functions</b> .....	4	<b>12 Layout</b> .....	37
<b>8 Specifications</b> .....	6	12.1 Layout Guidelines.....	37
8.1 Absolute Maximum Ratings.....	6	12.2 Layout Example.....	38
8.2 ESD Ratings.....	6	<b>13 Device and Documentation Support</b> .....	39
8.3 Recommended Operating Conditions.....	7	13.1 Device Support.....	39
8.4 Thermal Information.....	7	13.2 接收文档更新通知.....	39
8.5 Electrical Characteristics.....	7	13.3 支持资源.....	39
8.6 Typical Characteristics.....	11	13.4 Trademarks.....	39
<b>9 Detailed Description</b> .....	14	13.5 Electrostatic Discharge Caution.....	39
9.1 Overview.....	14	13.6 术语表.....	39
9.2 Functional Block Diagram.....	14	<b>14 Mechanical, Packaging, and Orderable Information</b> .....	39
9.3 Feature Description.....	15		

## 4 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision * (February 2022) to Revision A (April 2022)	Page
• 将文档状态从“预告信息”更改为“量产数据”.....	1

## 5 说明 (续)

该器件采用低关断  $I_Q$  和低  $I_Q$  睡眠模式，可尽可能减少无负载和轻负载条件下的电池消耗。该器件还支持采用旁路操作的超低  $I_Q$  深度睡眠模式，当电源电压大于升压输出调节目标时，无需外部旁路开关。可使用跟踪功能对此输出电压进行动态编程。

该器件的宽输入范围支持汽车冷启动和负载突降。当 **BIAS** 等于或大于 3.8V 时，最小输入电压可低至 0.8V。用户可通过外部电阻器对开关频率进行动态编程，编程范围为 100kHz 至 2.2MHz。2.2MHz 的开关频率可更大幅度地降低 **AM** 频带干扰，并支持实现小解决方案尺寸和快速瞬态响应。与转换器架构相比，控制器架构简化了严苛环境温度条件下的热管理性能。

该器件具有内置的保护功能，例如在  $V_{IN}$  范围内保持恒定的峰值电流限制、过压保护和热关断功能。外部时钟同步、可编程展频调制以及具有超低寄生效应的无引线封装有助于降低 **EMI** 并避免串扰问题。附加功能包括线路 UVLO、FPWM、二极管仿真、DCR 电感器电流检测、可编程的软启动和升压状态指示器。

## 6 Device Comparison Table

Device Option	Bypass Operation
LM5152-Q1	Enabled
LM51521-Q1	Disabled

## 7 Pin Configuration and Functions

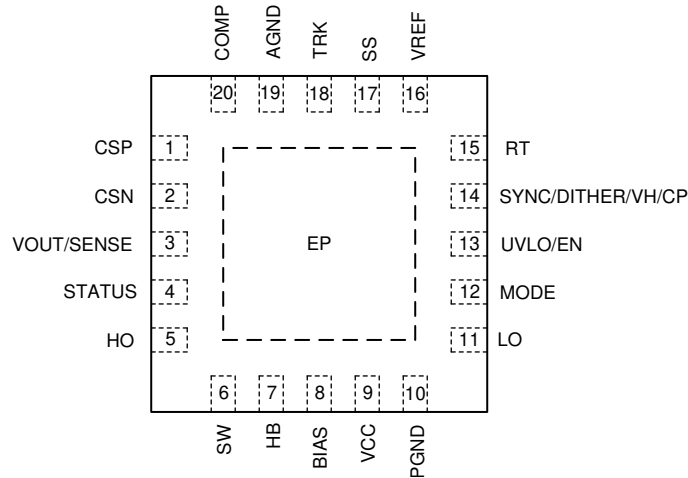


图 7-1. 20-Pin QFN with Wettable Flanks RGR Package (Top View)

表 7-1. Pin Functions

Pin		I/O <sup>(1)</sup>	Description
Name	NO.		
CSP	1	I	Current sense amplifier input. The pin operates as the positive input pin.
CSN	2	I	Current sense amplifier input. The pin operates as the negative input pin.
VOUT/SENSE	3	I	Output voltage sensing pin. An internal feedback resistor voltage divider is connected from the pin to AGND. Connect a 0.1- $\mu$ F local VOUT capacitor from the pin to ground.
			High-side MOSFET drain voltage sensing pin. Connect the pin to the drain of the high-side MOSFET through a short, low inductance path.
STATUS	4	O	Status indicator with an open-drain output stage. The internal pulldown switch opens when the output voltage is greater than the overvoltage threshold. The pin can be left floating if not used.
HO	5	O	High-side gate driver output. Connect directly to the gate of the high-side N-channel MOSFET through a short, low inductance path.
SW	6	P	Switching node connection and the high-side MOSFET source voltage sensing pin. Connect directly to the source of the high-side N-channel MOSFET and the drain of the low-side N-channel MOSFET through a short, low inductance path. Connect to PGND for a non-synchronous boost configuration.
HB	7	P	High-side driver supply for bootstrap gate drive. Boot diode is internally connected from VCC to this pin. Connect a 0.1- $\mu$ F capacitor between this pin and SW. Connect to VCC for a non-synchronous boost configuration.
BIAS	8	P	Supply voltage input to the VCC regulator. Connect a 1- $\mu$ F local BIAS capacitor from the pin to ground.
VCC	9	P	Output of the internal VCC regulator and supply voltage input of the internal MOSFET drivers. Connect a 4.7- $\mu$ F capacitor between the pin and PGND.
PGND	10	G	Power-ground pin. Connect directly to the source of the low-side N-channel MOSFET and the power ground plane through a short, low inductance path.
LO	11	O	Low-side gate driver output. Connect directly to the gate of the low-side N-channel MOSFET through a short, low inductance path.
MODE	12	I	Device switching mode (FPWM, diode emulation, or skip) selection pin. The device is configured to skip mode if the pin is open or if a resistor that is greater than 500 k $\Omega$ is connected from the pin to AGND during initial power-on. The device is configured to FPWM mode by connecting the pin to VCC or if the pin voltage is greater than 2.0 V during power-on. The device is configured to diode emulation mode by connecting the pin to ground or the pin voltage is less than 0.4 V during initial power-on. The switching mode can be dynamically programmed between FPWM and the DE mode during operation.

**表 7-1. Pin Functions (continued)**

Pin		I/O <sup>(1)</sup>	Description
Name	NO.		
UVLO/EN	13	I	Enable pin. The pin enables and disables the device. If the pin is less than 0.35 V, the device shuts down. The pin must be raised above 0.65 V to enable the device.
			Undervoltage lockout programming pin. The converter start-up and shutdown levels can be programmed by connecting the pin to the supply voltage through a resistor voltage divider. The low-side UVLO resistor must be connected to AGND. Connect to BIAS if not used.
SYNC/DITHER/VH/CP	14	I/O	Synchronization clock input. The internal oscillator can be synchronized to an external clock during operation. Connect to AGND if not used.
			Clock dithering and spread spectrum modulation frequency programming pin. If a capacitor is connected between the pin and AGND, the clock dithering and spread spectrum function is activated. During the dithering operation, the capacitor is charged and discharged with an internal 20- $\mu$ A current source or sink. As the voltage on the pin ramps up and down, the oscillator frequency is modulated between -6% and +5% of the nominal frequency set by the RT resistor. The clock dithering and spread spectrum can be deactivated during operation by pulling down the pin to ground.
			VCC hold pin. If the pin is greater than 2.0 V, the device holds the VCC pin voltage when the EN pin is grounded, which helps to restart quickly without reconfiguration.
			Charge pump enable pin. If the pin is greater than 2.0 V, the internal charge pump maintains the HB pin voltage above its HB UVLO threshold for bypass operation, which allows the high-side switch to turn on 100% during bypass operation (LM5152-Q1 only).
RT	15	I	Switching frequency setting pin. If no external clock is applied to the SYNC pin, the switching frequency is programmed by a single resistor between the pin and AGND. Switching frequency is dynamically programmable during operation.
VREF	16	I/O	1.0-V internal reference voltage output. Connect a 470-pF capacitor from the pin to AGND. The $V_{OUT}$ regulation target can be programmed by connecting a resistor voltage divider from the pin to TRK. The resistance from the pin to AGND must be always greater than 20 k $\Omega$ if used. Connect the low-side resistor of the divider to AGND.
			Boost converter output voltage can be dynamically programmed in the range of 5 V to 20 V during operation. The accuracy of the output voltage regulation is specified within the range. If the TRK pin voltage is externally controlled, the resistor voltage divider is not required.
SS	17	I/O	Soft-start time programming pin. An external capacitor and an internal current source set the ramp rate of the internal error amplifier reference during soft start. The device forces diode emulation during soft-start time.
TRK	18	I	Output regulation target programming pin. The $V_{OUT}$ regulation target can be programmed by connecting the pin to VREF through a resistor voltage divider or by controlling the pin voltage directly from a D/A. The recommended operating range of the pin is from 0.25 V to 1.0 V.
AGND	19	G	Analog ground pin. Connect to the analog ground plane through a wide and short path.
COMP	20	O	Output of the internal transconductance error amplifier. Connect the loop compensation components between the pin and AGND.
EP	—	—	Exposed pad of the package. The EP must be soldered to a large analog ground plane to reduce thermal resistance.

(1) G = Ground, I = Input, O = Output, P = Power

## 8 Specifications

### 8.1 Absolute Maximum Ratings

Over the recommended operating junction temperature range (unless otherwise specified)<sup>(1)</sup>

		MIN	MAX	UNIT
Input <sup>(2)</sup>	BIAS to AGND	- 0.3	50	V
	UVLO to AGND	- 0.3	BIAS + 0.3	
	CSP to AGND	- 0.3	50	
	CSP to CSN	- 0.3	0.3	
	VOUT to AGND	- 0.3	65	
	HB to AGND	- 0.3	65	
	HB to SW	- 0.3	5.8 <sup>(3)</sup>	
	SW to AGND	- 0.3	60	
	SW to AGND (50 ns)	- 1		
	MODE, SYNC, TRK to AGND	- 0.3	5.5	
	STATUS to AGND	- 0.3	VOUT + 0.3	
	RT to AGND	- 0.3	2.5	
	PGND to AGND	- 0.3	0.3	
Output <sup>(2)</sup>	VCC to AGND	- 0.3	5.8 <sup>(3)</sup>	V
	HO to SW (50 ns)	- 1		
	LO to PGND (50 ns)	- 1		
	VREF, SS, COMP to AGND <sup>(4)</sup>	- 0.3	5.5	
Operating junction temperature, T <sub>J</sub> <sup>(5)</sup>		- 40	150	°C
Storage temperature, T <sub>STG</sub>		- 55	150	

- (1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. *Absolute Maximum Ratings* do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If used outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) It is not allowed to apply an external voltage directly to VREF, COMP, SS, RT, LO, and HO pins.
- (3) Operating lifetime is de-rated when the pin voltage is greater than 5.5 V.
- (4) Maximum VREF pin sourcing current is 50  $\mu$  A.
- (5) High junction temperatures degrade operating lifetimes. Operating lifetime is de-rated for junction temperatures greater than 125°C.

### 8.2 ESD Ratings

			VALUE	UNIT	
V <sub>(ESD)</sub>	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 <sup>(1)</sup> HBM ESD Classification Level 2	±2000	V	
		Charged-device model (CDM), per AEC Q100-011 CDM ESD Classification Level C4B	All pins		±500
			Corner pins		±750

- (1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

### 8.3 Recommended Operating Conditions

Over the recommended operating junction temperature range (unless otherwise specified)<sup>(1)</sup>

		MIN	NOM	MAX	UNIT
V <sub>SUPPLY(BOOST)</sub>	Boost converter input (when BIAS ≥ 3.8 V)	0.8		42	V
V <sub>LOAD(BOOST)</sub>	Boost converter output	5		57 <sup>(3)</sup>	
V <sub>BIAS</sub>	BIAS input	3.8		42	
V <sub>UVLO</sub>	UVLO input	0		42	
V <sub>CSP</sub> , V <sub>CSN</sub>	Current sense input	0.8		42	
V <sub>VOUT</sub>	Boost output sense	5		57 <sup>(3)</sup>	
V <sub>TRK</sub>	TRK input	0.25		1	
V <sub>SYNC</sub>	Synchronization pulse input	0		5.25	
f <sub>SW</sub>	Typical switching frequency	100		2200	kHz
f <sub>SYNC</sub>	Synchronization pulse frequency	200		2200	
T <sub>J</sub>	Operating junction temperature <sup>(2)</sup>	-40		150	°C

- (1) *Recommended Operating Ratings* are conditions under the device is intended to be functional. For specifications and test conditions, see *Electrical Characteristics*.
- (2) High junction temperatures degrade operating lifetimes. Operating lifetime is de-rated for junction temperatures greater than 125°C.
- (3) V<sub>VOUT</sub> regulation target can be up to 20 V. The pin voltage should be less than or equal to 57 V.

### 8.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		RGR (QFN)	UNIT
		20 PINS	
R <sub>qJA</sub>	Junction-to-ambient thermal resistance	43.3	°C/W
R <sub>qJC(top)</sub>	Junction-to-case (top) thermal resistance	39.9	°C/W
R <sub>qJB</sub>	Junction-to-board thermal resistance	17.8	°C/W
γ <sub>JT</sub>	Junction-to-top characterization parameter	0.8	°C/W
γ <sub>JB</sub>	Junction-to-board characterization parameter	17.8	°C/W
R <sub>qJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	5.3	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

### 8.5 Electrical Characteristics

Typical values correspond to T<sub>J</sub> = 25°C. Minimum and maximum limits apply over T<sub>J</sub> = -40°C to 125°C. Unless otherwise stated, V<sub>BIAS</sub> = 12 V, V<sub>VOUT</sub> = 12 V, R<sub>T</sub> = 9.09 kΩ, R<sub>VREF</sub> = 65 kΩ

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
<b>SUPPLY CURRENT (BIAS, VCC, VOOUT)</b>						
I <sub>BIAS-SD</sub>	BIAS current in shutdown	V <sub>UVLO</sub> = 0 V, V <sub>OUT</sub> = 11.3 V		2.5	5	μA
I <sub>BIAS-DS1</sub>	BIAS current in deep sleep (skip or diode emulation mode, charge pump off, VCC is supplied by BIAS)	V <sub>UVLO</sub> = 2.5 V, V <sub>TRK</sub> = 0.25 V, V <sub>SYNC</sub> = 0 V, V <sub>OUT</sub> = 12 V		10	16	μA
I <sub>BIAS-DS2</sub>	BIAS current in deep sleep (FPWM mode, charge pump off, VCC is supplied by BIAS)	V <sub>UVLO</sub> = 2.5 V, V <sub>TRK</sub> = 0.25 V, V <sub>SYNC</sub> = 0 V, V <sub>OUT</sub> = 12 V		10	16	μA
I <sub>BIAS-DS3</sub>	BIAS current in deep sleep (skip or diode emulation mode, charge pump on, VCC is supplied by BIAS)	V <sub>UVLO</sub> = 2.5 V, V <sub>TRK</sub> = 0.25 V, V <sub>SYNC</sub> = 2.5 V, V <sub>OUT</sub> = 12 V		32	60	μA
I <sub>BIAS-DS4</sub>	BIAS current in deep sleep (FPWM mode, charge pump on, VCC is supplied by BIAS)	V <sub>UVLO</sub> = 2.5 V, V <sub>TRK</sub> = 0.25 V, V <sub>SYNC</sub> = 2.5 V, V <sub>OUT</sub> = 12 V		32	60	μA

## 8.5 Electrical Characteristics (continued)

Typical values correspond to  $T_J = 25^\circ\text{C}$ . Minimum and maximum limits apply over  $T_J = -40^\circ\text{C}$  to  $125^\circ\text{C}$ . Unless otherwise stated,  $V_{\text{BIAS}} = 12\text{ V}$ ,  $V_{\text{VOUT}} = 12\text{ V}$ ,  $R_T = 9.09\text{ k}\Omega$ ,  $R_{\text{VREF}} = 65\text{ k}\Omega$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I_{\text{BIAS-SLEEP}}$	BIAS current in sleep (skip mode, VCC is supplied by BIAS)	$V_{\text{UVLO}} = 2.5\text{ V}$ , $V_{\text{TRK}} = 0.25\text{ V}$ , MODE = OPEN, $V_{\text{OUT}} = 5\text{ V}$		13	17.5	$\mu\text{A}$
$I_{\text{BIAS-ACTIVE}}$	BIAS current in active (nonswitching, VCC is supplied by BIAS)	$V_{\text{UVLO}} = 2.5\text{ V}$ , $V_{\text{TRK}} = 0.6\text{ V}$ , MODE = VCC		1.2	1.5	mA
$I_{\text{VOUT-SD}}$	VOUT current in shutdown	$V_{\text{UVLO}} = 0\text{ V}$ , $V_{\text{OUT}} = 11.3\text{ V}$			1	$\mu\text{A}$
$I_{\text{VOUT-DS}}$	VOUT current in deep sleep (diode emulation mode)	$V_{\text{UVLO}} = 2.5\text{ V}$ , $V_{\text{TRK}} = 0.25\text{ V}$ , $V_{\text{OUT}} = 12\text{ V}$		1.2	1.5	$\mu\text{A}$
$I_{\text{VOUT-ACTIVE}}$	VOUT current in active (nonswitching)	$V_{\text{UVLO}} = 2.5\text{ V}$ , $V_{\text{TRK}} = 0.6\text{ V}$ , MODE = VCC		42	55	$\mu\text{A}$
$I_{\text{BATTERY-SD}}$	Battery drain in shutdown	$V_{\text{UVLO}} = 0\text{ V}$ , $V_{\text{OUT}} = 11.3\text{ V}$		2.5	5	$\mu\text{A}$
$I_{\text{BATTERY-DS1}}$	Battery drain in deep sleep (skip or diode emulation mode, charge pump off)	$V_{\text{UVLO}} = 2.5\text{ V}$ , $V_{\text{TRK}} = 0.25\text{ V}$ , $V_{\text{SYNC}} = 0\text{ V}$		11	17	$\mu\text{A}$
$I_{\text{BATTERY-DS2}}$	Battery drain in deep sleep (FPWM mode, charge pump off)	$V_{\text{UVLO}} = 2.5\text{ V}$ , $V_{\text{TRK}} = 0.25\text{ V}$ , $V_{\text{SYNC}} = 0\text{ V}$		11	17	$\mu\text{A}$
$I_{\text{BATTERY-DS3}}$	Battery drain in deep sleep (skip or diode emulation mode, charge pump on)	$V_{\text{UVLO}} = 2.5\text{ V}$ , $V_{\text{TRK}} = 0.25\text{ V}$ , $V_{\text{SYNC}} = 2.5\text{ V}$		33	62	$\mu\text{A}$
$I_{\text{BATTERY-DS4}}$	Battery drain in deep sleep (FPWM mode, charge pump on)	$V_{\text{UVLO}} = 2.5\text{ V}$ , $V_{\text{TRK}} = 0.25\text{ V}$ , $V_{\text{SYNC}} = 2.5\text{ V}$		33	62	$\mu\text{A}$
<b>ENABLE, UVLO</b>						
$V_{\text{EN-RISING}}$	Enable threshold	EN rising	0.45	0.55	0.65	V
$V_{\text{EN-FALLING}}$	Enable threshold	EN falling	0.35	0.45	0.55	V
$V_{\text{EN-HYS}}$	Enable hysteresis	EN falling	55	90	130	mV
$I_{\text{UVLO-HYS}}$	UVLO pulldown hysteresis current	$V_{\text{UVLO}} = 0.7\text{ V}$	8	10	12	$\mu\text{A}$
$V_{\text{UVLO-RISING}}$	UVLO threshold	UVLO rising	1.05	1.1	1.15	V
$V_{\text{UVLO-FALLING}}$	UVLO threshold	UVLO falling	1.025	1.075	1.125	V
$V_{\text{UVLO-HYS}}$	UVLO hysteresis	UVLO falling		25		mV
<b>SYNC/DITHER/VH/CP</b>						
$V_{\text{SYNC-RISING}}$	SYNC threshold/SYNC detection threshold	SYNC rising			2	V
$V_{\text{SYNC-FALLING}}$	SYNC threshold	SYNC falling	0.4			V
	Minimum SYNC pullup pulse width				100	ns
$I_{\text{DITHER}}$	Dither source and sink current		16	21	26	$\mu\text{A}$
$\Delta f_{\text{SW1}}$	$f_{\text{SW}}$ modulation (upper limit)			5%		
$\Delta f_{\text{SW2}}$	$f_{\text{SW}}$ modulation (lower limit)			-6%		
$V_{\text{DITHER-FALLING}}$	Dither disable threshold		0.65	0.75	0.85	V
<b>VCC</b>						
$V_{\text{VCC-REG1}}$	VCC regulation	$I_{\text{VCC}} = 100\text{ mA}$	4.75	5	5.25	V
$V_{\text{VCC-REG2}}$	VCC regulation	No load	4.75	5	5.25	V
$V_{\text{VCC-REG3}}$	VCC regulation during dropout	$V_{\text{BIAS}} = 3.8\text{ V}$ , $I_{\text{VCC}} = 100\text{ mA}$	3.45			V
$V_{\text{VCC-UVLO-RISING}}$	VCC UVLO threshold	VCC rising	3.55	3.65	3.75	V
$V_{\text{VCC-UVLO-FALLING}}$	VCC UVLO threshold	VCC falling	3.2	3.3	3.4	V



## 8.5 Electrical Characteristics (continued)

Typical values correspond to  $T_J = 25^\circ\text{C}$ . Minimum and maximum limits apply over  $T_J = -40^\circ\text{C}$  to  $125^\circ\text{C}$ . Unless otherwise stated,  $V_{\text{BIAS}} = 12\text{ V}$ ,  $V_{\text{VOUT}} = 12\text{ V}$ ,  $R_T = 9.09\text{ k}\Omega$ ,  $R_{\text{VREF}} = 65\text{ k}\Omega$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I_{\text{VCC-CL}}$	VCC sourcing current limit $V_{\text{VCC}} = 4\text{ V}$	100			mA
<b>CONFIGURATION (MODE)</b>					
$V_{\text{MODE-RISING}}$	FPWM mode threshold MODE rising			2.0	V
$V_{\text{MODE-FALLING}}$	Diode emulation mode threshold MODE falling	0.4			V
<b>RT</b>					
$V_{\text{RT}}$	RT regulation		0.5		V
<b>VREF, TRK, VOUT</b>					
$V_{\text{REF}}$	VREF regulation target	0.99	1	1.005	V
$V_{\text{OUT-REG}}$	VOUT regulation target1 with resistor divider VREF resistor divider to make $V_{\text{TRK}} = 0.25\text{ V}$ , $R_{\text{VREF}} = 65\text{ k}\Omega$	4.915	5	5.085	V
$V_{\text{OUT-REG}}$	VOUT regulation target2 with resistor divider VREF resistor divider to make $V_{\text{TRK}} = 0.5\text{ V}$ , $R_{\text{VREF}} = 65\text{ k}\Omega$	9.9	10	10.1	V
$V_{\text{OUT-REG}}$	VOUT regulation target3 with resistor divider VREF resistor divider to make $V_{\text{TRK}} = 1.0\text{ V}$ , $R_{\text{VREF}} = 65\text{ k}\Omega$	19.8	20	20.2	V
$V_{\text{OUT-REG}}$	VOUT regulation target1 using TRK $V_{\text{TRK}} = 0.25\text{ V}$ , $R_{\text{VREF}} = 65\text{ k}\Omega$	4.91	5	5.09	V
$V_{\text{OUT-REG}}$	VOUT regulation target2 using TRK $V_{\text{TRK}} = 0.5\text{ V}$ , $R_{\text{VREF}} = 65\text{ k}\Omega$	9.88	10	10.11	V
$V_{\text{OUT-REG}}$	VOUT regulation target3 using TRK $V_{\text{TRK}} = 1.0\text{ V}$ , $R_{\text{VREF}} = 65\text{ k}\Omega$	19.8	20	20.2	V
$I_{\text{TRK}}$	TRK bias current			1	$\mu\text{A}$
<b>SOFT START, DE to FPWM TRANSITION</b>					
$I_{\text{SS}}$	Soft-start current	17	20	23	$\mu\text{A}$
$V_{\text{SS-DONE}}$	MODE transition start SS rising	1.3	1.5	1.7	V
$R_{\text{SS}}$	SS pulldown switch $R_{\text{DS(ON)}}$		30	70	$\Omega$
$V_{\text{SS-DIS}}$	SS discharge detection threshold	30	50	75	mV
$V_{\text{SS-FB}}$	internal SS to FB clamp $V_{\text{FB}} = 0\text{ V}$		55	75	mV
<b>CURRENT SENSE (CSP, CSN, SW, SENSE)</b>					
$V_{\text{SLOPE}}$	Peak slope compensation amplitude Referenced to CS input		45		mV
$A_{\text{CS}}$	Current sense amplifier gain CSP = 3.0 V		10		V/V
	Current sense amplifier gain CSP = 1.5 V		10		V/V
$V_{\text{CLTH}}$	Positive peak current limit threshold (CSP-CSN) CSP = 3.0 V, MODE = GND	54	60	66	mV
	Positive peak current limit threshold (CSP-CSN) CSP = 1.5 V, MODE = GND	51	60	72	mV
$V_{\text{ZCD-DE}}$	ZCD threshold (SW-SENSE) MODE = GND		4		mV
$I_{\text{CSN}}$	CSN bias current			1	$\mu\text{A}$
$I_{\text{CSP}}$	CSP bias current		115		$\mu\text{A}$
<b>BOOT FAULT PROTECTION (HB)</b>					
	Maximum replenish pulse cycles		4		cycles
	Replenish off cycles		12		cycles
	Number of sets to enter hiccup mode protection		4		sets
	Off-cycle during hiccup mode off		512		cycles
<b>ERROR AMPLIFIER (COMP)</b>					

## 8.5 Electrical Characteristics (continued)

Typical values correspond to  $T_J = 25^\circ\text{C}$ . Minimum and maximum limits apply over  $T_J = -40^\circ\text{C}$  to  $125^\circ\text{C}$ . Unless otherwise stated,  $V_{\text{BIAS}} = 12\text{ V}$ ,  $V_{\text{VOUT}} = 12\text{ V}$ ,  $R_T = 9.09\text{ k}\Omega$ ,  $R_{\text{VREF}} = 65\text{ k}\Omega$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Gm	Transconductance			1		mA/V
I <sub>SOURCE-MAX</sub>	Maximum COMP sourcing current	$V_{\text{COMP}} = 0\text{ V}$	95			$\mu\text{A}$
I <sub>SINK-MAX</sub>	Maximum COMP sinking current	$V_{\text{COMP}} = 1.8\text{ V}$	90			$\mu\text{A}$
V <sub>CLAMP-MAX</sub>	COMP maximum clamp voltage	COMP rising	1.8	2.2	2.55	V
V <sub>CLAMP-MIN</sub>	COMP minimum clamp voltage, active in sleep and deep sleep mode	COMP falling		0.25		V
<b>PULSE WIDTH MODULATION (PWM)</b>						
f <sub>SW1</sub>	Switching frequency	$R_T = 220\text{ k}\Omega$	85	100	115	kHz
f <sub>SW2</sub>	Switching frequency	$R_T = 9.09\text{ k}\Omega$	1980	2200	2420	kHz
t <sub>ON-MIN</sub>	Minimum controllable on time	$R_T = 9.09\text{ k}\Omega$	14	20	50	ns
t <sub>OFF-MIN</sub>	Minimum forced off time	$R_T = 9.09\text{ k}\Omega$	70	95	115	ns
D <sub>MAX1</sub>	Maximum duty cycle limit	$R_T = 220\text{ k}\Omega$	90%	94%	98%	
D <sub>MAX2</sub>	Maximum duty cycle limit	$R_T = 9.09\text{ k}\Omega$	75%	80%	83%	
<b>LOW IQ SLEEP MODE</b>						
V <sub>WAKE</sub>	Internal wakeup threshold	VOUT falling (referenced to $V_{\text{OUT-REG}}$ )		98.5%		
	Sleep to wake-up delay	$R_T = 9.09\text{ k}\Omega$		5		$\mu\text{s}$
<b>STATUS, OVP</b>						
V <sub>OVTH-RISING</sub>	Overshoot threshold (OVP threshold, bypass mode threshold)	VOUT rising (referenced to $V_{\text{OUT-REG}}$ )	104.5%	108%	111%	
V <sub>OVTH-FALLING</sub>	Overshoot threshold (OVP threshold, bypass mode threshold)	VOUT falling (referenced to $V_{\text{OUT-REG}}$ )	100.5%	105%	109%	
R <sub>STATUS</sub>	STATUS pulldown switch $R_{\text{DSON}}$			90	180	$\Omega$
	Minimum BIAS for valid STATUS				2.5	V
<b>MOSFET DRIVER</b>						
	High-state voltage drop (HO driver)	100mA sinking		0.08	0.15	V
	Low-state voltage drop (HO driver)	100mA sourcing		0.04	0.1	V
	High-state voltage drop (LO driver)	100mA sinking		0.08	0.17	V
	Low-state voltage drop (LO driver)	100mA sourcing		0.04	0.1	V
V <sub>HB-UVLO</sub>	HB-SW UVLO threshold	HB-SW falling	2.2	2.5	3.0	V
I <sub>HB-SLEEP</sub>	HB quiescent current in sleep	HB-SW = 5 V		3.5	7	$\mu\text{A}$
t <sub>DHL</sub>	HO off to LO on dead time			20		ns
t <sub>DLH</sub>	LO off to HO on dead time			22		ns
	HB diode resistance			1.2		$\Omega$
<b>THERMAL SHUTDOWN</b>						
T <sub>TSD-RISING</sub>	Thermal shutdown threshold	Temperature rising		175		$^\circ\text{C}$
T <sub>TSD-HYS</sub>	Thermal shutdown hysteresis			15		$^\circ\text{C}$

## 8.6 Typical Characteristics

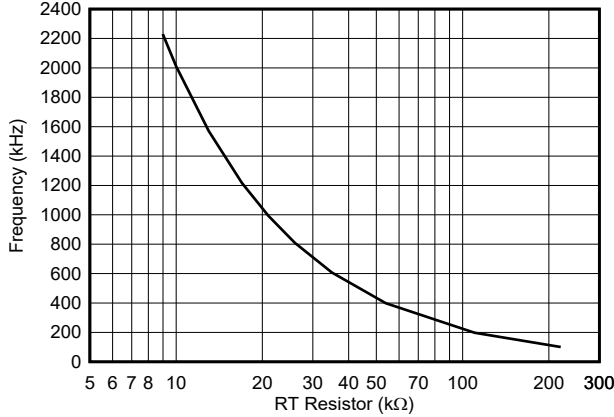


图 8-1. Frequency vs RT Resistance

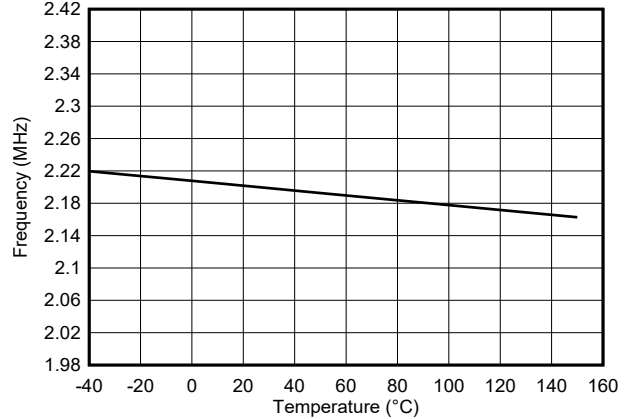


图 8-2. Frequency vs Temperature  
(RT = 9.09 kΩ, 2.2 MHz)

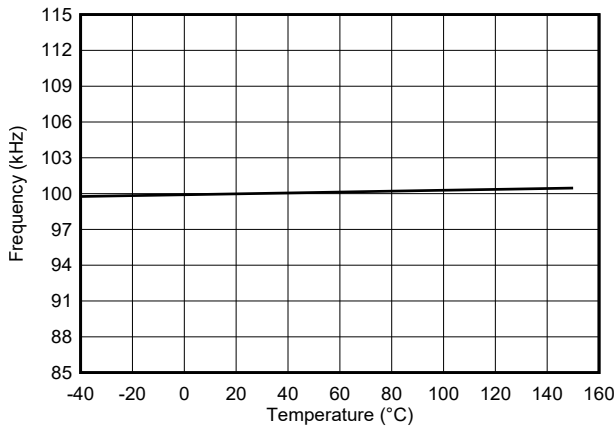


图 8-3. Frequency vs Temperature  
(RT = 220 kΩ, 100 kHz)

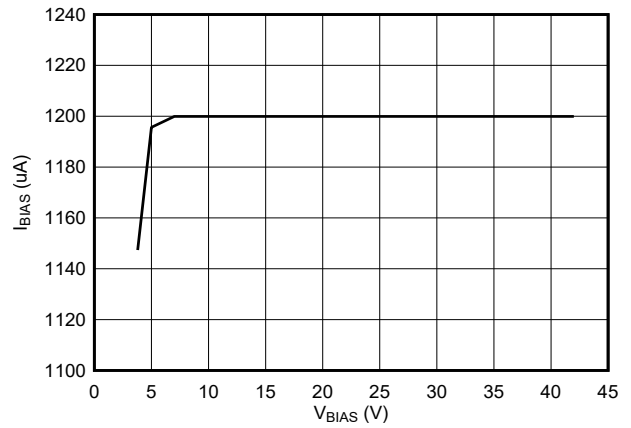


图 8-4. V<sub>BIAS</sub> vs I<sub>BIAS</sub> (Active Mode)

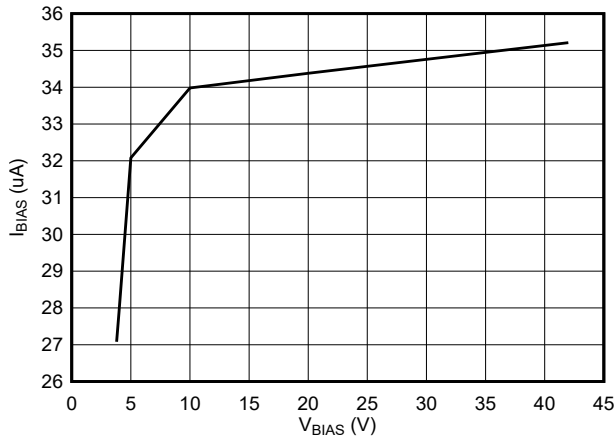


图 8-5. V<sub>BIAS</sub> vs I<sub>BIAS</sub> (Bypass Mode, Charge Pump On)

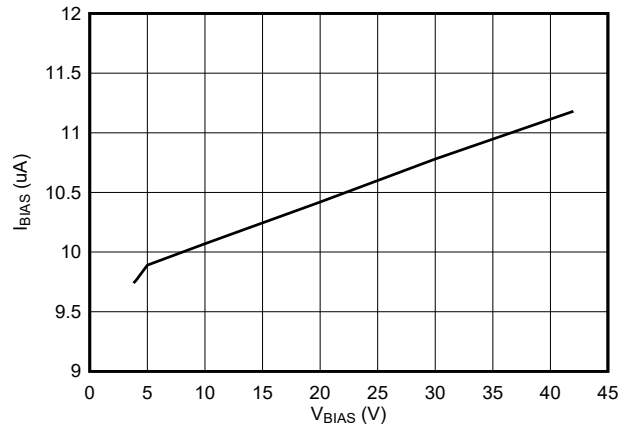


图 8-6. V<sub>BIAS</sub> vs I<sub>BIAS</sub> (Bypass Mode, Charge Pump Off)

## 8.6 Typical Characteristics (continued)

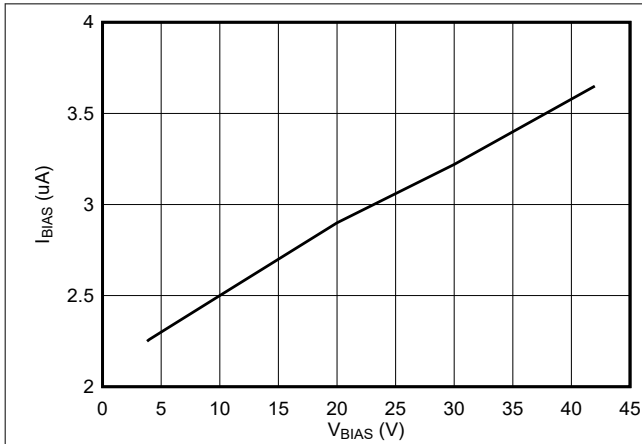


图 8-7.  $V_{BIAS}$  vs  $I_{BIAS}$  (Shutdown Mode)

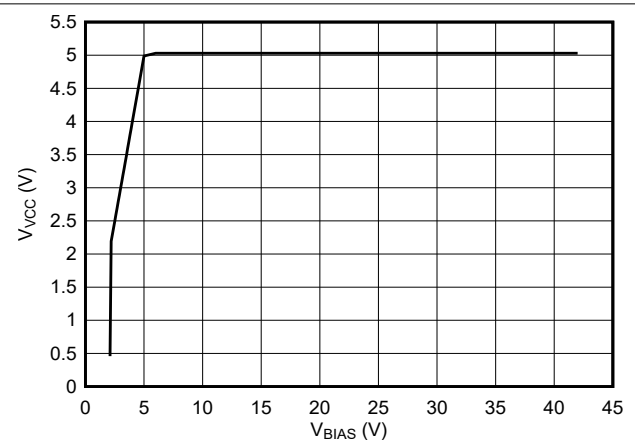


图 8-8.  $V_{BIAS}$  vs  $V_{VCC}$

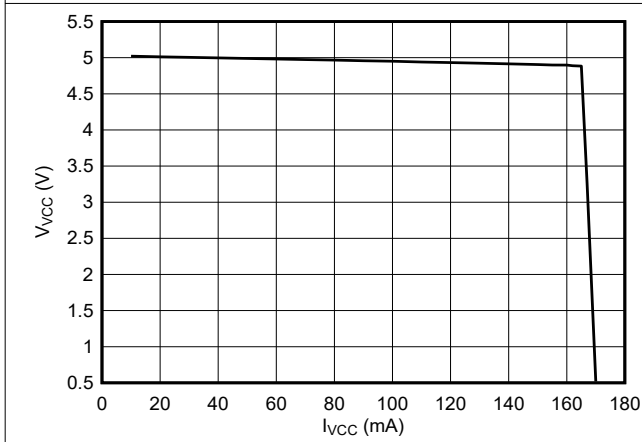


图 8-9.  $V_{VCC}$  vs  $I_{VCC}$

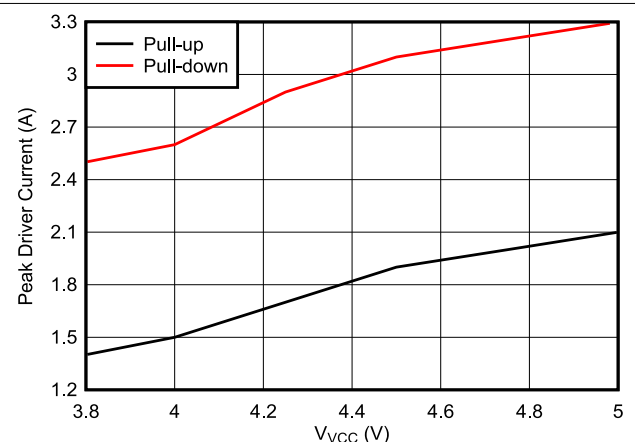


图 8-10.  $V_{VCC}$  vs Peak Driver Current

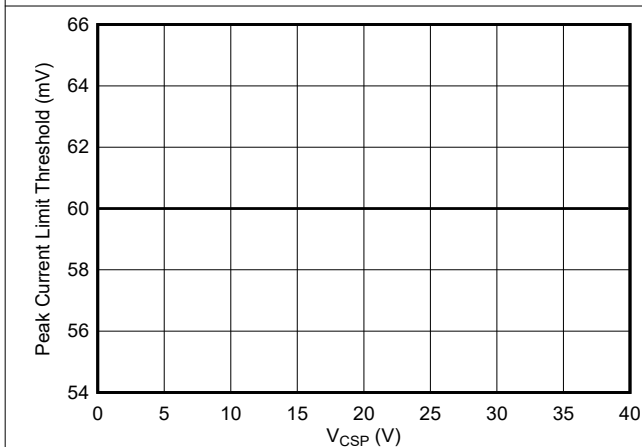


图 8-11. Peak Current Limit Threshold vs  $V_{CSP}$

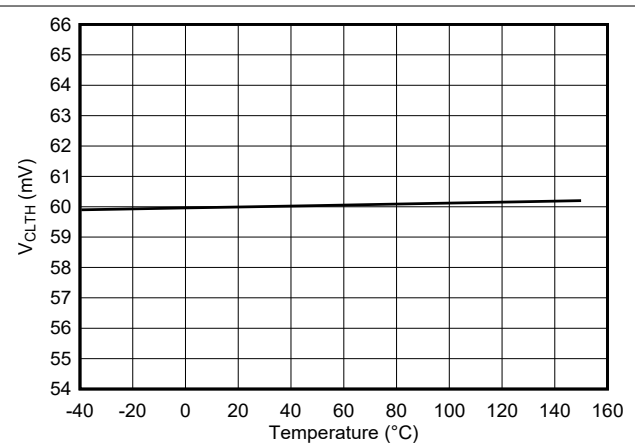


图 8-12. Peak Current Limit Threshold  $V_{CLTH}$  vs Temperature (CSP = 3 V)

### 8.6 Typical Characteristics (continued)

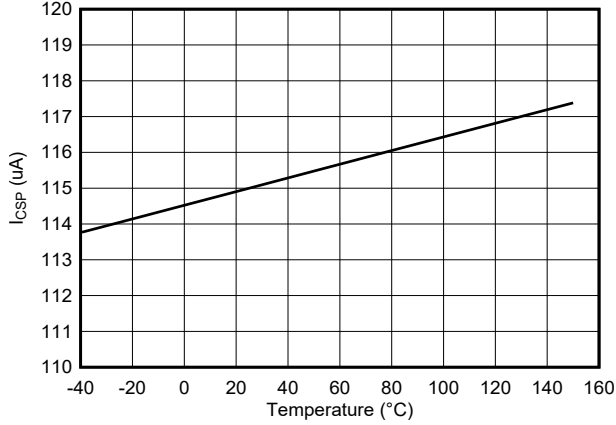


图 8-13.  $I_{CSP}$  vs Temperature (Active Mode)

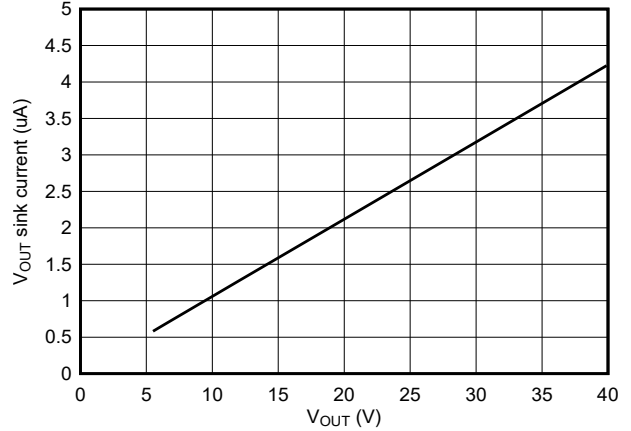


图 8-14.  $V_{OUT}$  Sink Current vs  $V_{OUT}$  (Deep Sleep)

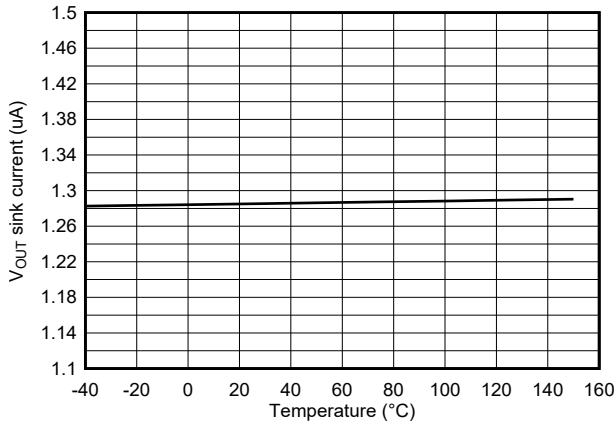


图 8-15.  $V_{OUT}$  Sink Current vs Temperature (Deep Sleep)

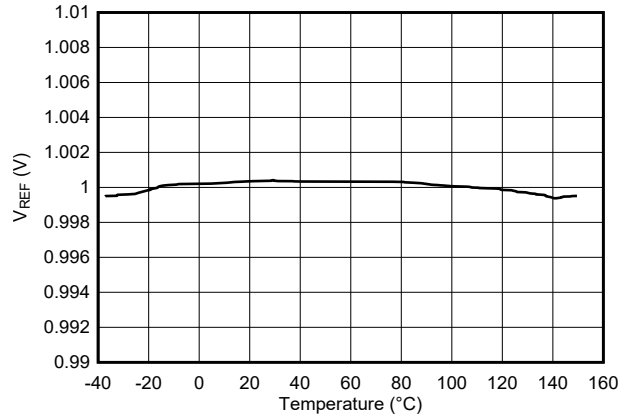


图 8-16.  $V_{REF}$  vs Temperature

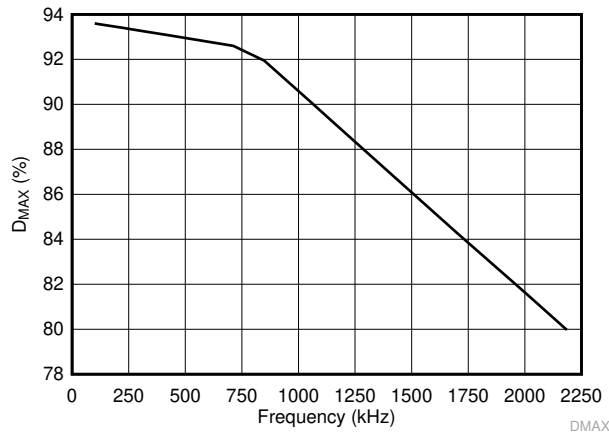


图 8-17.  $D_{MAX}$  vs Frequency

## 9 Detailed Description

### 9.1 Overview

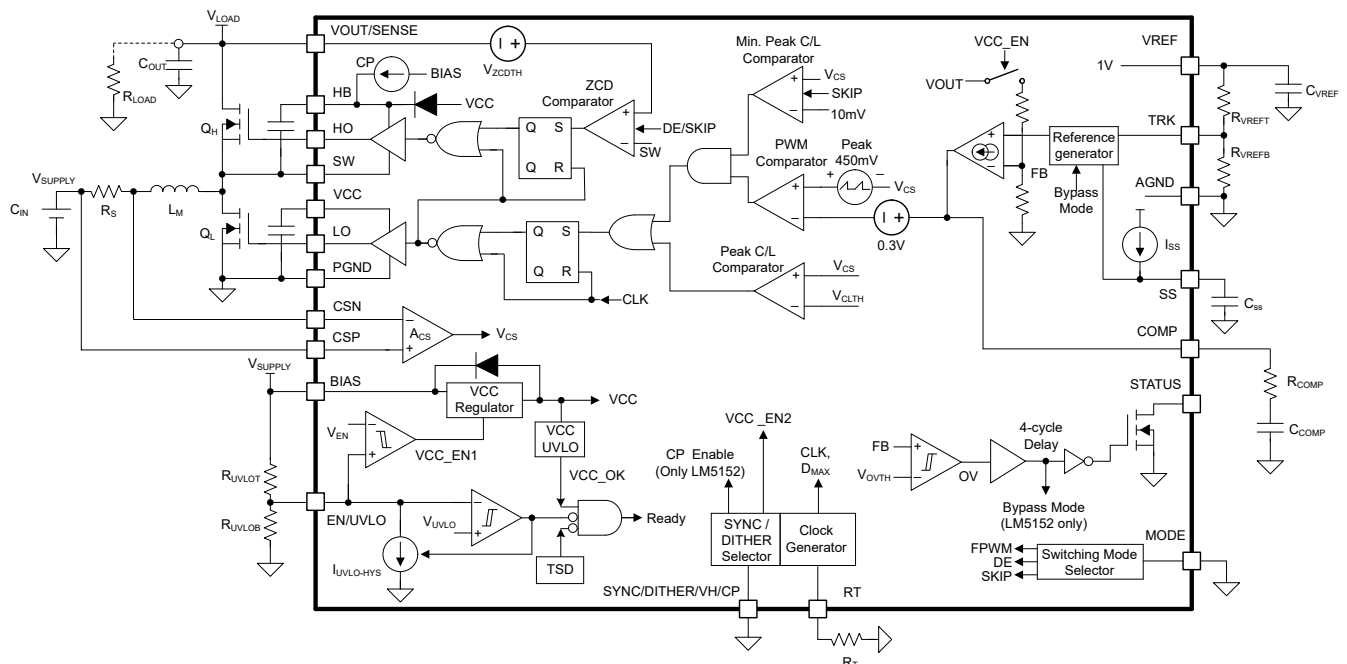
The LM5152x-Q1 (LM5152-Q1 and LM51521-Q1) device is a wide input range synchronous boost controller that employs peak current mode control. The device features a low shutdown  $I_Q$  and a low  $I_Q$  sleep mode, which minimizes battery drain at no and light load condition. The device also supports an ultra-low  $I_Q$  deep sleep mode with bypass operation, which eliminates the need for an external bypass switch when the supply voltage is greater than the boost output regulation target. The output voltage can be dynamically programmed using the tracking function.

The wide input range of the device supports automotive cold-crank and load dump. The minimum input voltage can be as low as 0.8 V when BIAS is equal to or greater than 3.8 V. The switching frequency is dynamically programmed with an external resistor from 100 kHz to 2.2 MHz. Switching at 2.2 MHz minimizes AM band interference and allows for a small solution size and fast transient response. Controller architecture simplifies thermal management at harsh ambient temperature conditions when compared to converter architectures.

The device has built-in protection features such as peak current limit, which is constant over  $V_{IN}$ , overvoltage protection, and thermal shutdown. External clock synchronization, programmable spread spectrum modulation, and a lead-less package with minimal parasitic help reduce EMI and avoid cross talk. Additional features include the following:

- Line UVLO
- FPWM
- Diode emulation
- DCR inductor current sensing
- Programmable soft start
- Boost status indicator

### 9.2 Functional Block Diagram



## 9.3 Feature Description

### 备注

Read through 节 9.4 before reading the feature description of the device. It is recommended to understand which device functional modes and what type of light load switching modes are supported by the device.

The parameters or thresholds values mentioned in this section are reference values unless otherwise specified. Refer to the [Electrical Characteristics](#) to find the minimum, maximum, and typical values.

### 9.3.1 Device Enable/Disable (EN, VH Pin)

The device shuts down when EN is less than the EN threshold ( $V_{EN}$ ) and VH is less than the SYNC threshold ( $V_{SYNC}$ ). The device is enabled when EN is greater than  $V_{EN}$  or VH is greater than  $V_{SYNC}$ . The VH pin provides a 40- $\mu$ s internal delay before the device shuts down.

During shutdown, a 33-k $\Omega$  internal pulldown resistor on the EN pin is connected to GND to prevent a false turn-on when the pin is floating. Once EN goes above the EN threshold ( $V_{EN}$ ), the 33-k $\Omega$  resistor is disconnected and the  $I_{UVLO-HYS}$  current source is enabled to provide the UVLO functionality. The  $I_{UVLO-HYS}$  current is designed to avoid chatter around the EN threshold voltage.

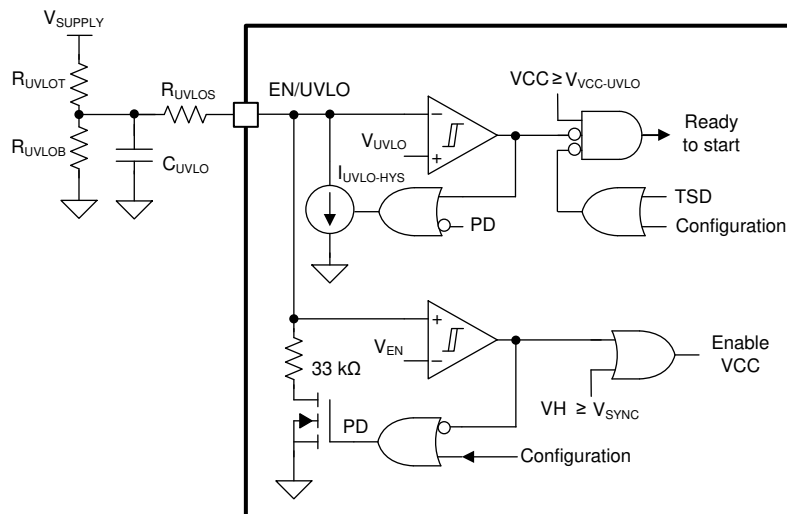


图 9-1. EN/UVLO Circuit

### 9.3.2 High Voltage VCC Regulator (BIAS, VCC Pin)

The device features a high voltage 5-V VCC regulator, which is sourced from the BIAS pin. The internal VCC regulator turns on 50  $\mu$ s after the device is enabled and the 120- $\mu$ s device configuration starts when VCC is above the VCC UVLO threshold ( $V_{VCC-UVLO}$ ). The device configuration is reset when the device shuts down or VCC falls down below 2.2 V. The preferred way to reconfigure the device is to shut down the device. During the configuration time, the light load switching mode is selected.

The high voltage VCC regulator allows the connection of the BIAS pin directly to supply voltages from 3.8 V to 42 V. When BIAS is less than the 5-V VCC regulation target ( $V_{VCC-REG}$ ), the VCC output tracks the BIAS pin voltage with a small dropout voltage, which is caused by the 1.7- $\Omega$  resistance of the VCC regulator.

The recommended VCC capacitor value is 4.7  $\mu$ F. The VCC capacitor should be populated between VCC and PGND as close to the device as possible. The recommended BIAS capacitor value is 1.0  $\mu$ F. The BIAS capacitor must be populated between BIAS and PGND close to the device.

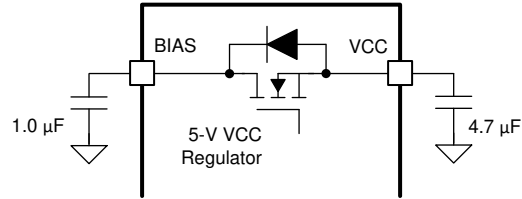


图 9-2. High Voltage VCC Regulator

The VCC regulator features a VCC current limit function that prevents device damage when the VCC pin is shorted to ground accidentally. The minimum sourcing capability of the VCC regulator is 100 mA ( $I_{VCC-CL}$ ) during either the device configuration time or active mode operation. The minimum sourcing capability of the VCC regulator is reduced to 1 mA during sleep mode or deep sleep mode, or when EN is less than  $V_{EN}$  and  $V_H$  is greater than  $V_{SYNC}$ . The VCC regulator supplies the internal drivers and other internal circuits. The external MOSFETs must be carefully selected to make the driver current consumption less than  $I_{VCC-CL}$ . The driver current consumption can be calculated in [方程式 1](#).

$$I_G = 2 \times Q_{G@5V} \times f_{SW} \quad (1)$$

where

- $Q_{G@5V}$  is the N-channel MOSFET gate charge at 5-V gate-source voltage.

If VIN operation below 3.8 V is required, the BIAS pin must be connected to the output of the boost converter ( $V_{LOAD}$ ). By connecting the BIAS pin to  $V_{LOAD}$ , the boost converter input voltage ( $V_{SUPPLY}$ ) can drop down to 0.8 V if BIAS is greater than 3.8 V. See [节 9.3.16](#) for more detailed information about the minimum  $V_{SUPPLY}$ .

### 9.3.3 Light Load Switching Mode Selection (MODE Pin)

The light load switching mode is selected during the device configuration. The device is configured to skip mode when the MODE pin is floating or a resistor that is greater than 500 k $\Omega$  is connected between MODE and AGND during the device configuration. Once the device is configured to skip mode, the light load switching mode cannot be changed until the user reconfigures the device.

If the MODE pin voltage is less than 0.4 V ( $V_{MODE-FALLING}$ ) or grounded during the device configuration, the device is configured to diode emulation (DE) mode. If the MODE pin voltage is greater than 2.0 V ( $V_{MODE-RISING}$ ) or connected to VCC during the device configuration, the device is configured to forced PWM (FPWM) mode. If the device is configured to DE or FPWM mode, light load switching mode can be dynamically changed between DE and FPWM modes during operation without reconfiguration.

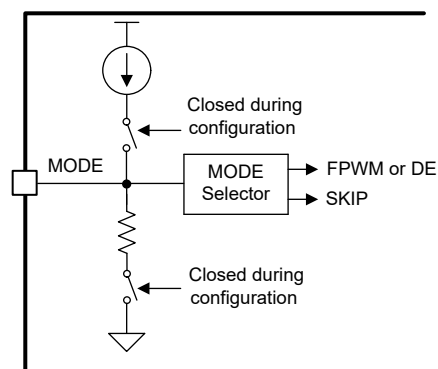


图 9-3. MODE Selection Circuit

### 9.3.4 Line Undervoltage Lockout (UVLO Pin)

When UVLO is greater than the UVLO threshold ( $V_{UVLO}$ ), the device enters active mode if the device configuration is finished. UVLO hysteresis is accomplished with an internal 25-mV voltage hysteresis ( $V_{UVLO-HYS}$ )



at the UVLO pin, and an additional 10- $\mu$ A current sink ( $I_{UVLO-HYS}$ ) that is switched on or off. When the UVLO pin voltage exceeds  $V_{UVLO}$ , the current sink is disabled to quickly raise the voltage at the UVLO pin. When the UVLO pin voltage falls below  $V_{UVLO}$  or during the device configuration time, the current sink is enabled, causing the voltage at the UVLO pin to fall quickly.

The external UVLO resistor voltage divider ( $R_{UVLOT}$ ,  $R_{UVLOB}$ ) must be designed so that the voltage at the UVLO pin is greater than  $V_{UVLO}$  when  $V_{SUPPLY}$  is in the desired operating range. The values of  $R_{UVLOT}$  and  $R_{UVLOB}$  can be calculated as follows.

$$R_{UVLOT} = \frac{\left( V_{SUPPLY\_ON} - \frac{V_{UVLO\_RISING}}{V_{UVLO\_FALLING}} \times V_{SUPPLY\_OFF} \right)}{I_{UVLO\_HYS}} \quad (2)$$

$$R_{UVLOB} = \frac{V_{UVLO\_FALLING} \times R_{UVLOT}}{V_{SUPPLY\_OFF} - V_{UVLO\_FALLING}} \quad (3)$$

A UVLO capacitor ( $C_{UVLO}$ ) is required in case  $V_{SUPPLY}$  drops below  $V_{SUPPLY-OFF}$  momentarily during the start-up or during a severe load transient at the low input voltage. If the required UVLO capacitor is large, an additional series UVLO resistor ( $R_{UVLOS}$ ) can be used to quickly raise the voltage at the UVLO pin when  $I_{UVLO-HYS}$  is disabled.

The UVLO pin can be connected to the BIAS pin if not used. Drive the UVLO pin through a minimum of a 5-k $\Omega$  resistor if the BIAS pin voltage is less than the UVLO pin voltage in any conditions.

### 9.3.5 Fast Restart Using VCC HOLD (VH Pin)

The device is prepared for a fast start or restart when VH is greater than  $V_{SYNC}$ . The device configuration is completed and the VCC regulator is active. The device stops switching, but keeps the VCC regulator active when EN is less than  $V_{EN}$  and VH is greater than  $V_{SYNC}$  (see 图 9-5).

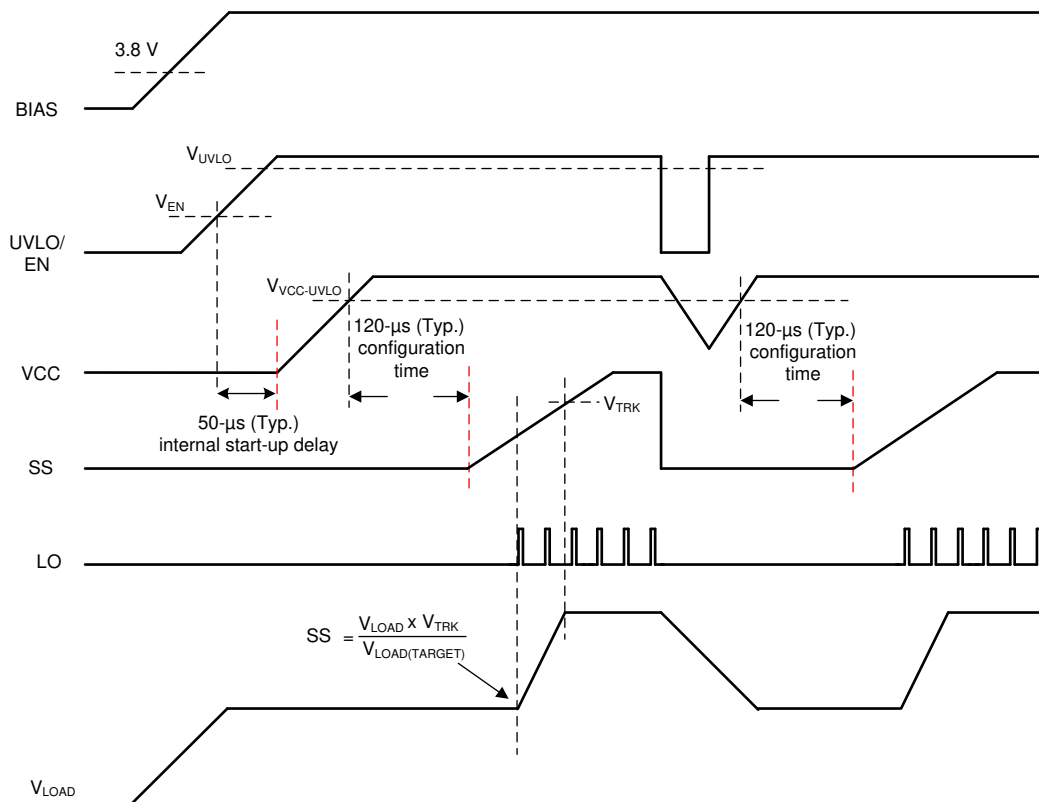


图 9-4. Boost Start-Up Waveforms Case 1: Start-Up by EN/UVLO, Restart when  $VH < V_{SYNC}$

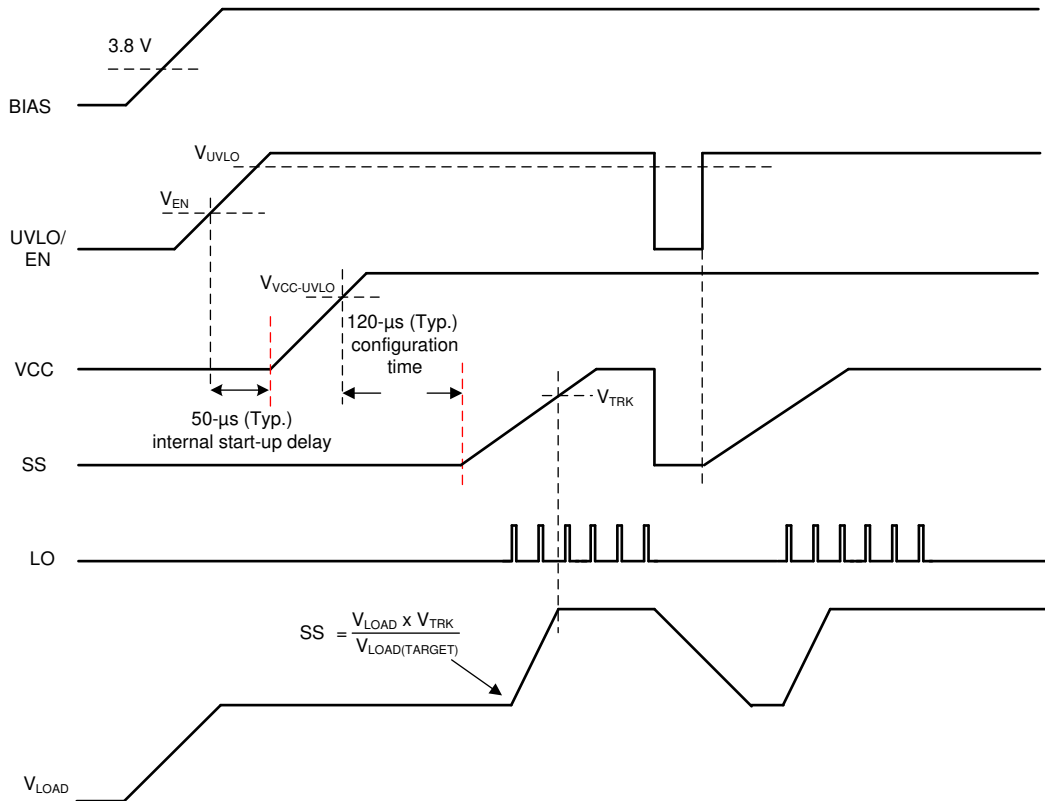


图 9-5. Boost Start-Up Waveforms Case 2: Start-Up by EN/UVLO, Restart when  $V_H > V_{SYNC}$

### 9.3.6 Adjustable Output Regulation Target ( $V_{OUT}$ , TRK, VREF Pin)

The  $V_{OUT}$  regulation target ( $V_{OUT-REG}$ ) is adjustable by programming the TRK pin voltage, which is the reference of the internal error amplifier. The accuracy of  $V_{OUT-REG}$  is given when the TRK voltage is between 0.25 V and 1.0 V. The high impedance TRK pin allows users to program the pin voltage directly by a D/A converter or by connecting to a resistor voltage divider ( $R_{VREFB}$ ,  $R_{VREFB}$ ) between VREF and AGND.

The device provides a 1-V voltage reference ( $V_{REF}$ ), which can be used to program the TRK pin voltage through a resistor voltage divider. It is not recommended to use  $V_{REF}$  as a reference voltage of an external circuit because the device periodically disables  $V_{REF}$  in sleep or deep sleep mode. For stability reasons, the VREF capacitor ( $C_{VREF}$ ) should be between 330 pF and 1 nF. 470 pF is recommended.

When  $R_{VREFB}$  and  $R_{VREFB}$  are used to program the TRK pin voltage,  $V_{OUT-REG}$  can be calculated as follows.

$$V_{OUT\_REG} = \frac{20 \times R_{VREFB}}{R_{VREFB} + R_{VREFB}} \quad (4)$$

The TRK pin voltage can be dynamically programmed in active mode, which makes an envelope tracking power supply design easy. When designing a tracking power supply, it is required to adjust the TRK pin voltage slow enough so that the  $V_{OUT}$  pin voltage can track the command and the internal overvoltage or undervoltage comparator is not triggered during the transient operation. An RC filter must be used at the TRK pin to slow down the slew rate of the command signal at the TRK pin, especially when a step input is applied. When a trapezoidal or sinusoidal input is applied, the slew rate or the frequency of the command signal must be limited.

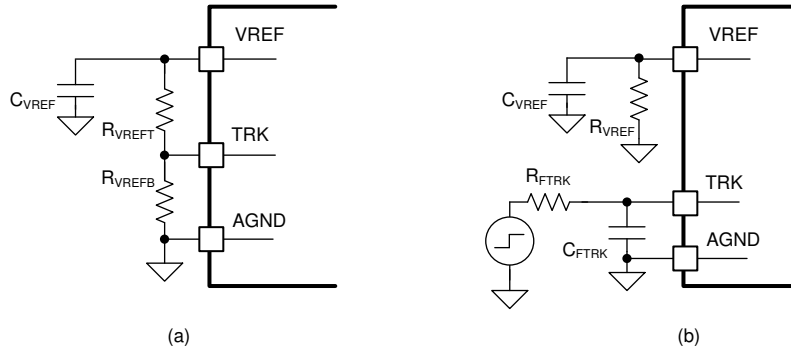


图 9-6. TRK Control (a) Using VREF (b) by External Step Input

$V_{OUT-REG}$  tracks the TRK pin voltage in all operation modes (FPWM, skip or diode mode) with a maximum of a 20-ms delay during deep sleep mode to save power. Take extra care when programming TRK if  $V_{SUPPLY}$  is greater than  $V_{OUT-REG}$  in any conditions. The device enters active mode with a 5- $\mu$ s delay if  $V_{LOAD}$  falls below  $V_{OUT-REG}$  in deep sleep mode, but the device enters active mode with maximum of a 20-ms delay if  $V_{OUT-REG}$  is increased by TRK above  $V_{LOAD}$  in deep sleep mode.

### 9.3.7 Overvoltage Protection (VOUT Pin)

The device provides an overvoltage protection (OVP) for boost converter output. The OVP comparator monitors the VOUT pin through internal resistor voltage dividers. If the VOUT pin voltage rises above the overvoltage threshold ( $V_{OVTH}$ ), OVP is activated. When OVP is triggered, the device turns off the low-side driver and turns on the high-side driver until zero current is detected in diode emulation or skip mode. In FPWM mode, the low-side driver is not turned off when the OVP is triggered.

After at least 40  $\mu$ s in OVP status, the device enters deep sleep mode and LM5152-Q1 turns on the high-side driver 100% while LM51521-Q1 turns the high-side driver off. The recommended VOUT capacitor ( $C_{VOUT}$ ) is 0.1  $\mu$ F.

### 9.3.8 Boost Status Indicator (STATUS Pin)

The device provides a boost status indicator (STATUS) to simplify sequencing and supervision. STATUS is an open-drain output. A pullup resistor between 5 k $\Omega$  and 100 k $\Omega$  can be externally connected to the STATUS pin. The STATUS switch opens four cycles after the VOUT pin voltage is greater than the overvoltage voltage ( $V_{OVTH}$ ). The STATUS pin is pulled down to ground when the following occurs:

- VOUT pin voltage is less than  $V_{OVTH}$ .
- UVLO is less than  $V_{UVLO}$ .
- VCC is less than  $V_{VCC-UVLO}$ .
- During thermal shutdown

The STATUS pin voltage cannot be greater than  $V_{VOUT} + 0.3$  V.

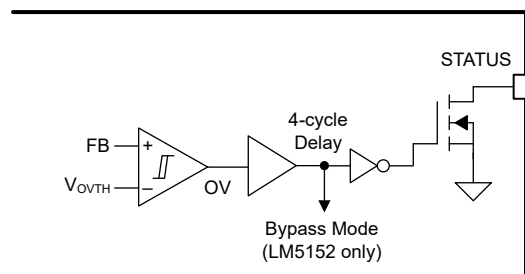


图 9-7. STATUS Indicator

### 9.3.9 Dynamically Programmable Switching Frequency (RT)

The switching frequency of the device is set by a single RT resistor connected between RT and AGND if no external synchronization clock is applied to the SYNC pin. The resistor value to set the RT switching frequency ( $R_T$ ) is calculated as follows.

$$R_T = \frac{2.21 \times 10^{10}}{f_{RT(\text{typical})}} - 955 \quad (5)$$

The RT pin is regulated to 0.5 V by an internal RT regulator when the device is in active mode or during the device configuration. The switching frequency can be dynamically programmed during operation as shown in [图 9-8](#).

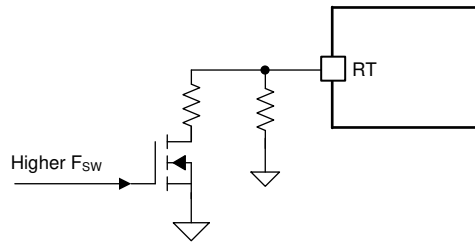


图 9-8. Frequency Hopping Example

### 9.3.10 External Clock Synchronization (SYNC Pin)

The switching frequency of the device can be synchronized to an external clock by directly applying an external pulse signal to the SYNC pin. The internal clock is synchronized at the rising edge of the external synchronization pulse using an internal PLL. Connect the SYNC pin to ground if not used.

The external synchronization pulse must be greater than  $V_{\text{SYNC}}$  in the high logic state and must be less than  $V_{\text{SYNC}}$  in the low logic state. The duty cycle of the external synchronization pulse is not limited, but the minimum on-pulse and the minimum off-pulse widths must be greater than 100 ns. The frequency of the external synchronization pulse must satisfy [方程式 6](#) and [方程式 7](#).

$$200\text{kHz} \leq f_{\text{SYNC}} \leq 2.2\text{MHz} \quad (6)$$

$$0.75 \times f_{RT(\text{typical})} \leq f_{\text{SYNC}} \leq 1.5 \times f_{RT(\text{typical})} \quad (7)$$

For example, a RT resistor is required for typical 350-kHz switching to cover 263-kHz to 525-kHz clock synchronization without changing the RT resistor.

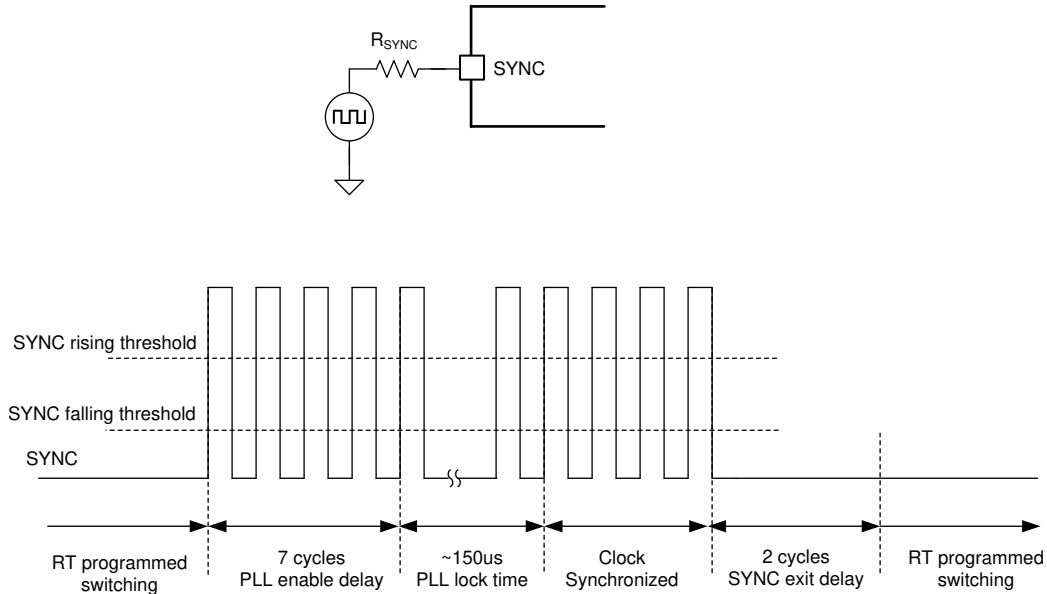


图 9-9. External Clock Synchronization

Drive the SYNC pin through a minimum 1-k $\Omega$  resistor if the BIAS pin voltage is less than the SYNC pin voltage in any conditions.

### 9.3.11 Programmable Spread Spectrum (DITHER Pin)

The device provides an optional programmable spread spectrum (clock dithering) function that is activated by connecting a capacitor between DITHER and AGND. A triangular waveform centered at 1.0 V is generated across the dither capacitor. This triangular waveform modulates the oscillator frequency by -6% to +5% of the frequency set by the RT resistor. The dither capacitance value sets the rate of the low frequency modulation.

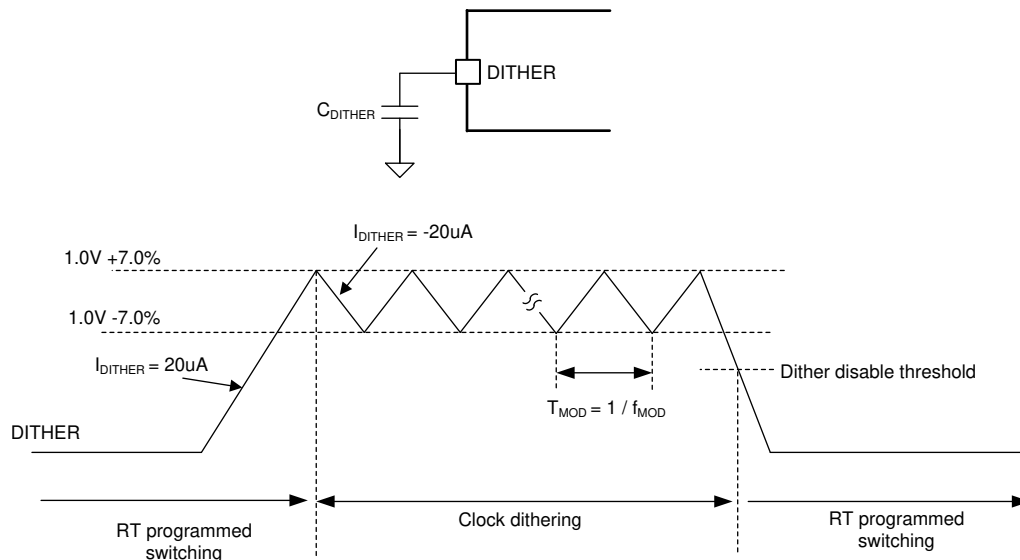


图 9-10. Switching Frequency Dithering

For the dithering circuit to effectively reduce peak EMI, the modulation frequency must be much less than the RT switching frequency. The dither capacitance, which is required for a given modulation frequency ( $f_{MOD}$ ), can be calculated from 方程式 8. Setting the  $f_{MOD}$  to 9 kHz or 10 kHz is a good starting point.

$$C_{DITHER} = \frac{20\mu A}{f_{MOD} \times 0.29} \quad (8)$$

Connecting DITHER to AGND deactivates clock dithering, and the internal oscillator operates at a fixed frequency set by the RT resistor. Clock dithering is also disabled when an external synchronization pulse is applied.

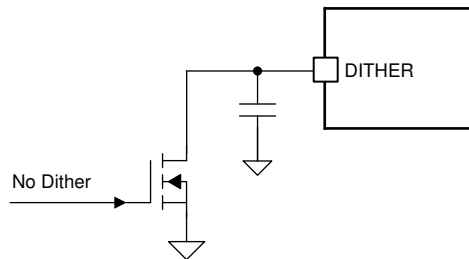


图 9-11. Dynamic Dither On/Off Example

Connecting STATUS to DITHER enables the clock dithering when the STATUS pin is pulled down to ground and also enables the internal charge pump during bypass operation when the STATUS pin is pulled up.

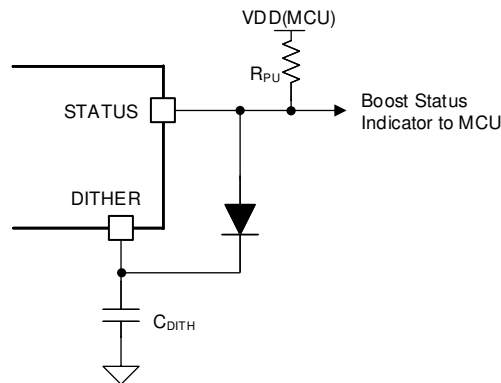


图 9-12. Enable Clock Dithering and Internal Charge Pump Together

### 9.3.12 Programmable Soft Start (SS Pin)

The soft-start feature helps the converter gradually reach the steady state operating point. To reduce start-up stresses and surges, the device regulates the error amplifier reference to the SS pin voltage or the TRK pin voltage ( $V_{TRK}$ ), whichever is lower.

The internal 20- $\mu$  A soft-start ( $I_{SS}$ ) current turns on 120  $\mu$  s after the VCC pin crosses  $V_{VCC-UVLO}$ .  $I_{SS}$  gradually increases the voltage on an external soft-start capacitor ( $C_{SS}$ ). This results in a gradual rise of the output voltage.

In FPWM mode, the device forces diode emulation while the SS pin voltage is less than 1.5 V. When the SS pin voltage is greater than 1.5 V, the device changes the zero current detection (ZCD) threshold gradually from 4 mV to -145 mV to achieve a smooth transition from diode emulation to FPWM mode.

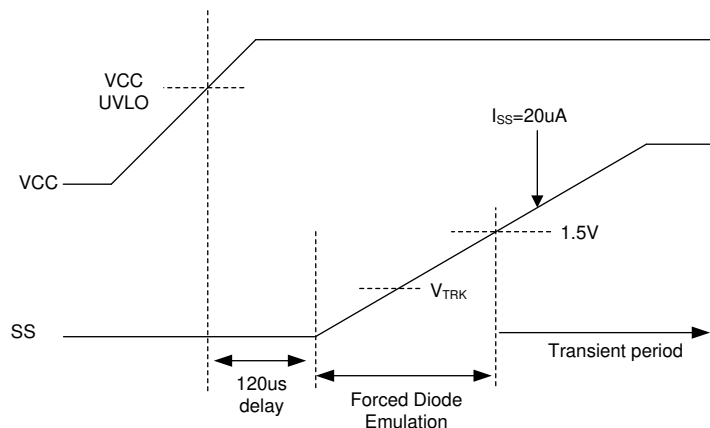


图 9-13. Soft Start and Smooth Transition to FPWM

In boost topology, the soft-start time ( $t_{SS}$ ) varies with the input supply voltage because the boost output voltage is equal to the boost input voltage at the beginning of the soft-start switching.  $t_{SS}$  in boost topology is calculated with 方程式 9.

$$t_{SS} = V_{TRK} \times \frac{C_{SS}}{20\mu A} \times \left(1 - \frac{V_{SUPPLY}}{V_{LOAD}}\right) \quad (9)$$

In general, it is recommended to choose a soft-start time long enough so that the converter can start up without going into an overcurrent state. If the device is used for a pre-boost in automotive application, it is recommended to use 100-pF  $C_{SS}$  to reach steady state as soon as possible.

The device also features an internal SS-to-FB clamp ( $V_{SS-FB}$ ), which clamps SS 55 mV above FB and is activated if 256 consecutive switching cycles occur with current limit. The SS-to-FB clamp is deactivated if 32 consecutive switching cycles occur without exceeding the current limit threshold. This clamp helps to minimize surges after output shorts or over load situations. The device can enter deep sleep mode when SS is greater than 1.5 V. It is not recommended to pulldown SS to stop switching.

### 9.3.13 Wide Bandwidth Transconductance Error Amplifier and PWM (TRK, COMP Pin)

The device includes an internal feedback resistor voltage divider. The internal feedback resistor voltage divider is connected to the negative input of the internal transconductance error amplifier, and the TRK pin voltage programs the positive input of the internal transconductance error amplifier after the soft start is finished. The internal transconductance error amplifier features high output resistance ( $R_O = 10 \text{ M}\Omega$ ) and wide bandwidth ( $BW = 3 \text{ MHz}$ ) and sinks (or sources) current, which is proportional to the difference between the negative and the positive inputs of the error amplifier.

The output of the error amplifier is connected to the COMP pin, allowing the use of a Type-2 loop compensation network.  $R_{COMP}$ ,  $C_{COMP}$ , and an optional  $C_{HF}$  loop compensation components configure the error amplifier gain and phase characteristics to achieve a stable loop response. This compensation network creates a pole at very low frequency, a mid-band zero, and a high frequency pole.

The PWM comparator in 图 9-14 compares the sum of the amplified sensed inductor current and the slope compensation ramp with the sum of the COMP pin voltage and a -0.3-V internal offset, and terminates the present cycle if the sum of the amplified sensed inductor current and the slope compensation ramp is greater than the sum of the COMP pin voltage and the -0.3-V internal offset.

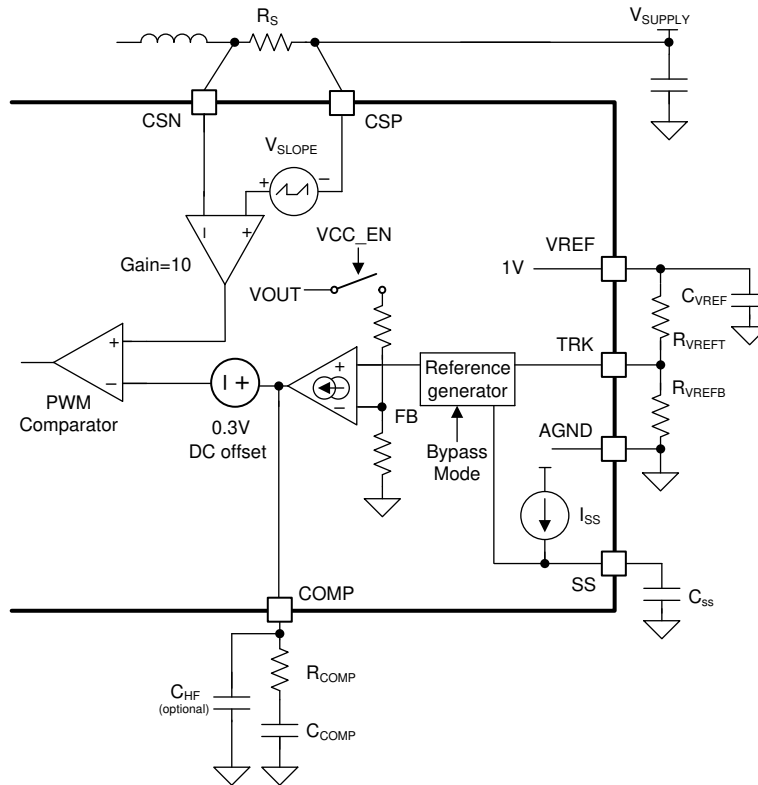


图 9-14. Error Amplifier, Current Sense Amplifier, and PWM

9.3.14 Current Sensing and Slope Compensation (CSP, CSN Pin)

The device features a current sense amplifier with an effective gain of 10 ( $A_{CS}$ ), and provides an internal slope compensation ramp to the PWM comparator to prevent a subharmonic oscillation at high duty cycle. The device generates the 45-mV peak slope compensation ramp ( $V_{SLOPE}$ ) at the input of the current sense amplifier, which is a 0.45-V peak (at 100% duty cycle) slope compensation ramp at the PWM comparator input.

According to peak current mode control theory, the slope of the slope compensation ramp must be greater than at least half of the sensed inductor current falling slope to prevent subharmonic oscillation at high duty cycle. Therefore, the minimum amount of the slope compensation must satisfy 方程式 10.

$$0.5 \times (V_{LOAD} - V_{SUPPLY}) / L_M \times R_S \times \text{Margin} < V_{SLOPE} \times f_{SW} \text{ (in Boost)} \tag{10}$$

where

- 1.5-1.7 is recommended as the margin to cover non-ideal factors.

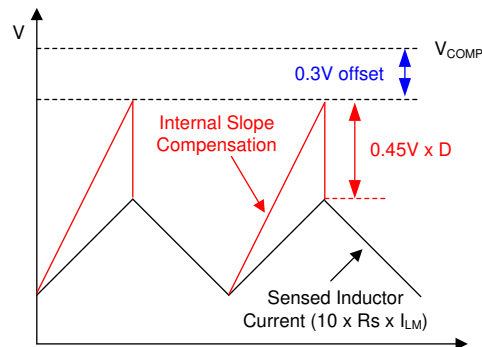


图 9-15. PWM Comparator Input



### 9.3.15 Constant Peak Current Limit (CSP, CSN Pin)

When the CSP-CSN voltage exceeds the 60-mV cycle-by-cycle current limit threshold ( $V_{CLTH}$ ), the current limit comparator immediately terminates the LO output. The device provides an constant peak current limit whose peak inductor current limit is constant over the input and output voltage. For the case where the inductor current can overshoot, such as inductor saturation, the current limit comparator skips pulses until the current has decayed below the current limit threshold.

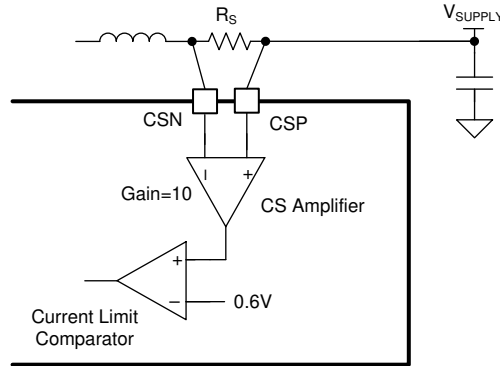


图 9-16. Current Limit Comparator

Cycle-by-cycle peak current limit is calculated as follows:

$$I_{PEAK-CL} = \frac{0.06}{R_S} \quad (11)$$

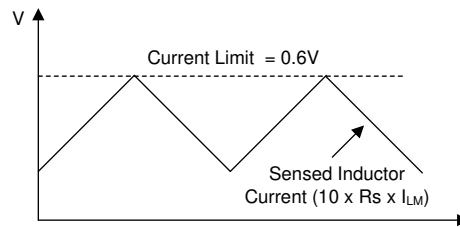


图 9-17. Current Limit Comparator Input

Boost converters have a natural pass-through path from the supply to the load through the high-side MOSFET body diode. Due to this path, boost converters cannot provide the peak current limit protection when the output voltage is close to or less than the input supply voltage, especially the peak current limit protection that does not work during the minimum on time ( $t_{ON-MIN}$ ).

### 9.3.16 Maximum Duty Cycle and Minimum Controllable On-Time Limits

The device provides the maximum duty cycle limit ( $D_{MAX}$ ) and minimum off time to cover the non-ideal factors caused by resistive elements.  $D_{MAX}$  decides the minimum input supply voltage ( $V_{SUPPLY(MIN)}$ ), which can achieve the target output voltage ( $V_{LOAD}$ ) during CCM operation, but  $V_{SUPPLY(MIN)}$ , which can achieve the target output voltage during DCM operation, is not limited by  $D_{MAX}$ .  $V_{SUPPLY(MIN)}$ , which can achieve the target output voltage during CCM operation, can be estimated as follows. See also 图 8-17.

$$V_{SUPPLY(MIN)} \approx V_{LOAD} \times (1 - D_{MAX}) + I_{SUPPLY(MAX)} \times (R_{DCR} + R_S + R_{DS(ON)}) \quad (12)$$

where

- $I_{SUPPLY(MAX)}$  is the maximum input current at  $V_{SUPPLY(MIN)}$ .
- $R_{DCR}$  is the DC resistance of the inductor.
- $R_{DS(ON)}$  is the turn-on resistance of the MOSFET.

At very light-load condition or when  $V_{\text{SUPPLY}}$  is close to  $V_{\text{OUT-REG}}$ , the device skips the low-side driver pulses if the required on time is less than  $t_{\text{ON-MIN}}$ . This pulse skipping appears as a random behavior. If  $V_{\text{SUPPLY}}$  is further increased to the voltage higher than  $V_{\text{OUT-REG}}$ , the required on time becomes 0 and eventually the device can start bypass operation (LM5152-Q1 only), which turns on the high-side driver 100% when the  $V_{\text{OUT}}$  pin voltage is greater than  $V_{\text{OVTH}}$ .

### 9.3.17 Deep Sleep Mode and Bypass Operation (HO, CP Pin)

When SS is greater than 1.5 V, the device enters deep sleep mode after at least 40  $\mu\text{s}$  in OVP status. The device re-enters active mode if  $V_{\text{OUT}}$  falls down below  $V_{\text{OVP}}$ . During bypass operation, the loss, which is caused by the body diode of the high-side MOSFET, is minimized. The high-side driver of the LM51521-Q1 does not turn on in the deep sleep mode. See 节 9.4.1.5 for more information.

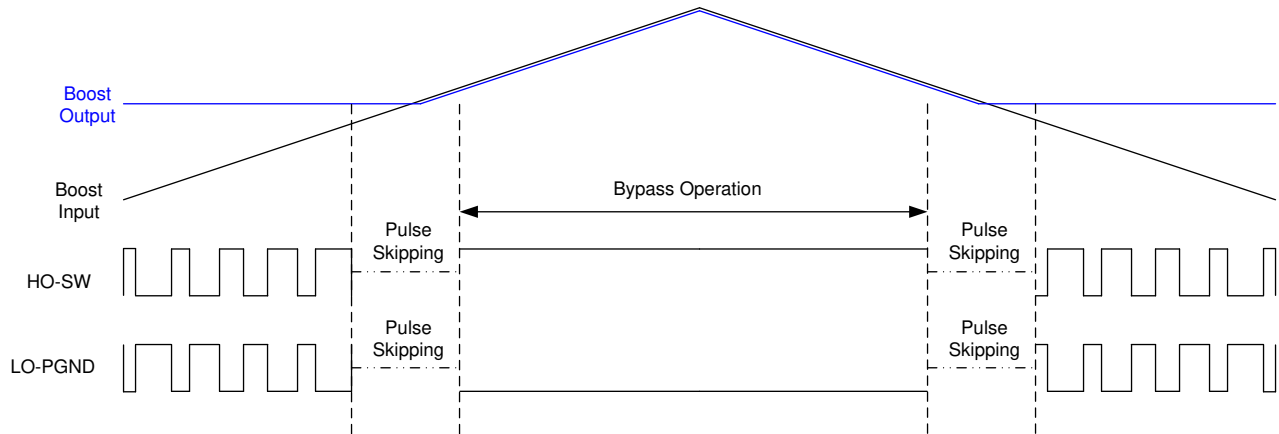


图 9-18. PWM to Bypass Transition in CCM Operation

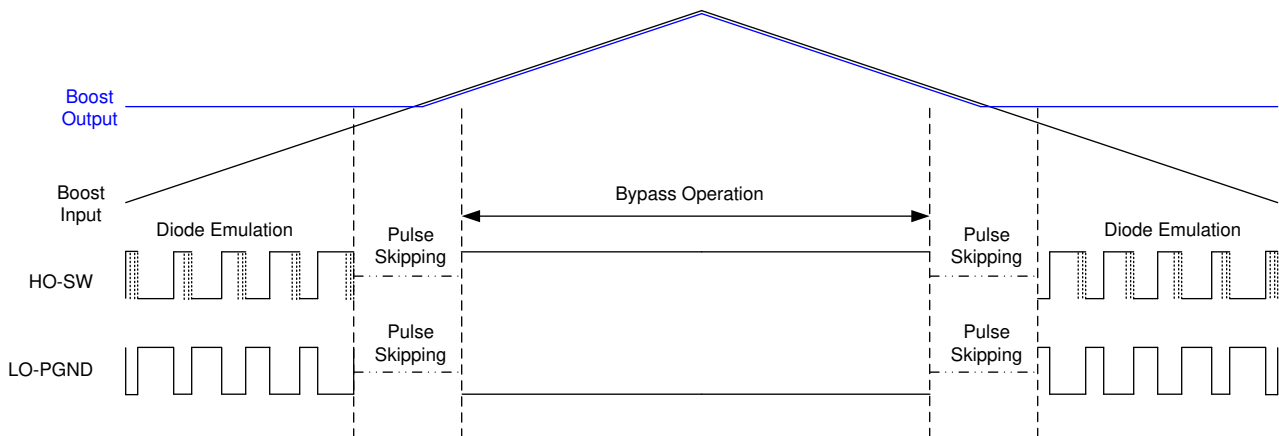


图 9-19. PWM to Bypass Transition in DCM Operation

### 9.3.18 MOSFET Drivers, Integrated Boot Diode, and Hiccup Mode Fault Protection (LO, HO, HB Pin)

The device provides N-channel logic MOSFET drivers, which can source a peak current of 2.2 A and sink a peak current of 3.3 A. The LO driver is powered by VCC, and is enabled when EN is greater than  $V_{\text{EN}}$  and VCC is greater than  $V_{\text{VCC-UVLO}}$ . The HO driver is powered by HB, and is enabled when EN is greater than  $V_{\text{EN}}$  and HB-SW voltage is greater than HB UVLO threshold ( $V_{\text{HB-UVLO}}$ ).

When the SW pin voltage is approximately 0 V by turning on the low-side MOSFET, the  $C_{\text{HB}}$  is charged from VCC through the internal boot diode. The recommended value of the  $C_{\text{HB}}$  is 0.1  $\mu\text{F}$ .

The LO and HO outputs are controlled with an adaptive dead-time methodology, which makes sure that both outputs are not turned on at the same time. When the device commands LO to be turned on, the adaptive dead-time logic first turns off HO and waits for HO-SW voltage to drop. LO is then turned on after a small delay ( $t_{\text{DHL}}$ ).

Similarly, the HO driver turn-on is delayed until the LO-PGND voltage has discharged. HO is then turned on after a small delay ( $t_{DLH}$ ).

If the BIAS pin voltage is below the 5-V VCC regulation target, take extra care when selecting the MOSFETs. The gate plateau voltage of the MOSFET switch must be less than the BIAS pin voltage to completely enhance the MOSFET, especially during start-up at low BIAS pin voltage. If the driver output voltage is lower than the MOSFET gate plateau voltage during start-up, the converter may not start up properly and it can stick at the maximum duty cycle in a high-power dissipation state. This condition can be avoided by selecting a lower threshold MOSFET or by turning on the device when the BIAS pin voltage is sufficient. Care should be taken when the converter operates in bypass at any conditions. During the bypass operation, the minimum HO-SW voltage is 3.75 V.

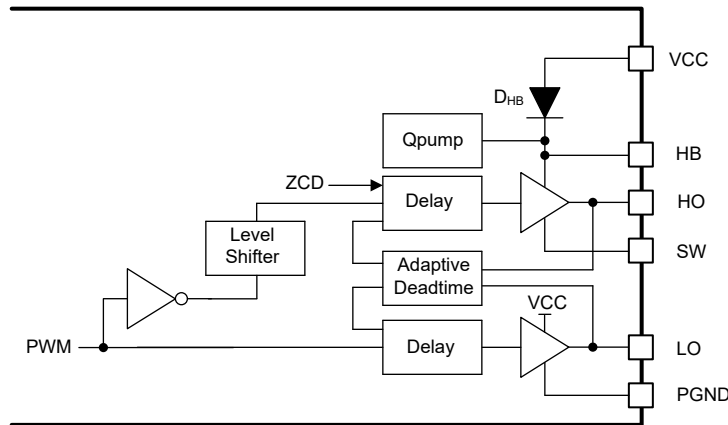


图 9-20. Driver Structure with Internal Boot Diode

The hiccup mode fault protection is triggered by the HB UVLO. If the HB-SW voltage is less than the HB UVLO threshold ( $V_{HB-UVLO}$ ), the LO turns on by force for 75 ns to replenish the boost capacitor. The device allows up to four consecutive replenish switching. After the maximum four consecutive boot replenish switching, the device skips switching for 12 cycles. If the device fails to replenish the boost capacitor after the four sets of the four consecutive replenish switching, the device stops switching and enters 512 cycles of hiccup mode off time. During the hiccup mode off time, SS is grounded.

If required, the slew rate of the switching node voltage can be adjusted by adding a gate resistor in parallel with a pulldown PNP transistor. Extra care should be taken when adding the gate resistor because it can decrease the effective dead time.

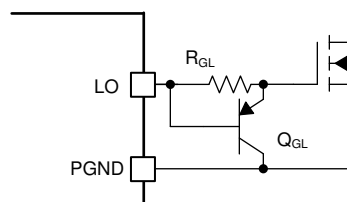


图 9-21. Slew Rate Control

### 9.3.19 Thermal Shutdown Protection

An internal thermal shutdown (TSD) is provided to protect the device if the junction temperature ( $T_J$ ) exceeds 175°C. When TSD is activated, the device is forced into a low-power thermal shutdown state with the MOSFET drivers and the VCC regulator disabled. After the  $T_J$  is reduced (typical hysteresis is 15°C), the device restarts. The TSD is disabled during sleep or deep sleep mode.

## 9.4 Device Functional Modes

### 9.4.1 Device Status

#### 9.4.1.1 Shutdown Mode

When EN is less than  $V_{EN}$  and VH is less than  $V_{SYNC}$ , the device shuts down, consuming  $3\ \mu\text{A}$  from BIAS. In shutdown mode, COMP, SS, and STATUS are grounded. The device is enabled when EN is greater than  $V_{EN}$  or VH is greater than  $V_{SYNC}$ .

#### 9.4.1.2 Configuration Mode

When the device is enabled initially, the  $120\text{-}\mu\text{s}$  device configuration starts if VCC is greater than  $V_{VCC-UVLO}$ . During device configuration, the light load switching mode is selected. The device configuration is reset when the device shuts down or VCC falls down below 2.2 V. The preferred way to reconfigure the device is to shut down the device. During the configuration time, a  $33\text{-k}\Omega$  internal EN pulldown resistor is connected, the minimum sourcing capability of the VCC regulator is 100 mA and the RT pin is regulated to 0.5 V by the internal RT regulator.

#### 9.4.1.3 Active Mode

After the  $120\text{-}\mu\text{s}$  initial device configuration is finished, the device enters active mode with all functions enabled if UVLO is greater than  $V_{UVLO}$ . In active mode, a soft-start sequence starts and the error amplifier is enabled.

#### 9.4.1.4 Sleep Mode

When skip mode is selected as the light load switching mode and SS is greater than 1.5 V, the device enters sleep mode if the low-side driver skips switching for 16 consecutive cycles. Once the device enters sleep mode, the device cannot re-enter active mode during  $8\text{-}\mu\text{s}$  minimum sleep time. During sleep mode, the device stops the internal oscillator to reduce the operating current, disables UVLO comparator, disables the error amplifier, and parks the COMP pin at 0.25 V. The device re-enters active mode if the VOUT pin voltage falls down below the wake up threshold ( $V_{WAKE}$ ), which is 1.1% lower than  $V_{OUT-REG}$ .

#### 9.4.1.5 Deep Sleep Mode

When SS is greater than 1.5 V, the device enters deep sleep mode after four cycles in OVP status. During deep sleep mode, the device stops the internal oscillator to reduce the operating current, disables UVLO comparator, disables the error amplifier, and parks the COMP pin at 0.25 V.

In FPWM or DE mode, the device re-enters active mode if  $V_{OUT}$  falls down below  $V_{OVTH}$ . In skip mode, the device re-enters active mode if VOUT falls down below  $V_{OVTH}$ , then immediately enters sleep mode after 16 consecutive cycles of pulse skipping.

### 9.4.2 Light Load Switching Mode

The device provides three light load switching modes. Inductor current waveforms in each mode are different at the light or no load condition.

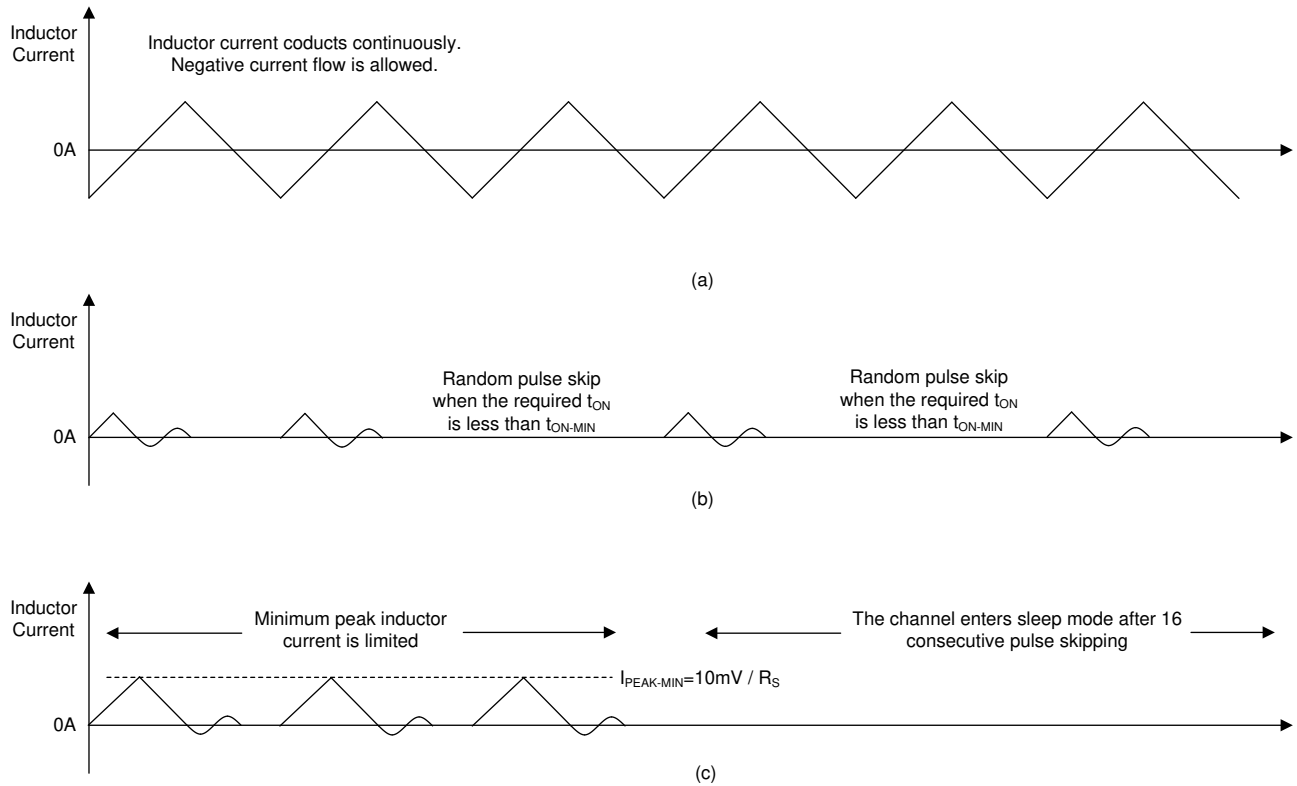


图 9-22. Inductor Current Waveform at Light Load (a) FPWM (b) Diode Emulation (c) Skip Mode

#### 9.4.2.1 Forced PWM (FPWM) Mode

In FPWM mode, the inductor current conducts continuously at light or no load conditions, allowing a continuous conduction mode (CCM) operation. The benefits of FPWM mode are a fast light load to heavy load transient response and constant switching frequency at light or no load conditions. The maximum reverse current is limited to  $145 \text{ mV}/R_{DS(ON)}$  in FPWM mode.

#### 9.4.2.2 Diode Emulation (DE) Mode

In diode emulation (DE) mode, inductor current flow is allowed only in one direction - from the input source to the output load. The device monitors the SENSE-SW voltage during the high-side switch on time and turns off the high-side switch for the remainder of the PWM cycle when the SENSE-SW voltage falls down below the 5-mV zero current detection (ZCD) threshold ( $V_{ZCD}$ ). The benefit of the diode emulation is a higher efficiency than FPWM mode efficiency at light load condition.

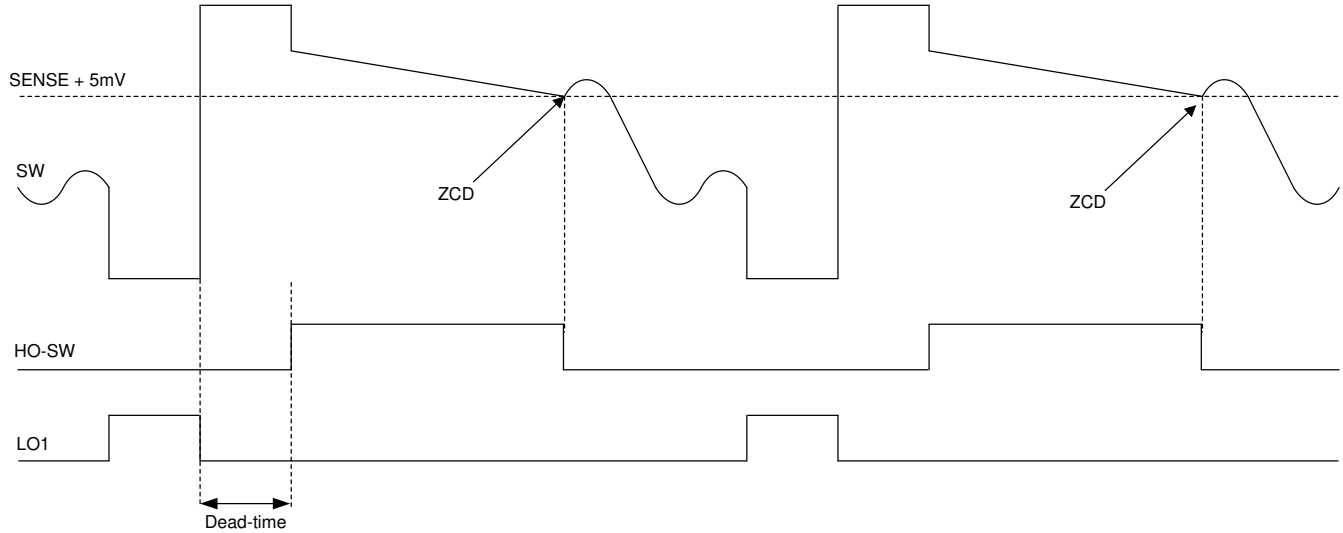


图 9-23. Zero Current Detection

#### 9.4.2.3 Forced Diode Emulation Operation in FPWM Mode

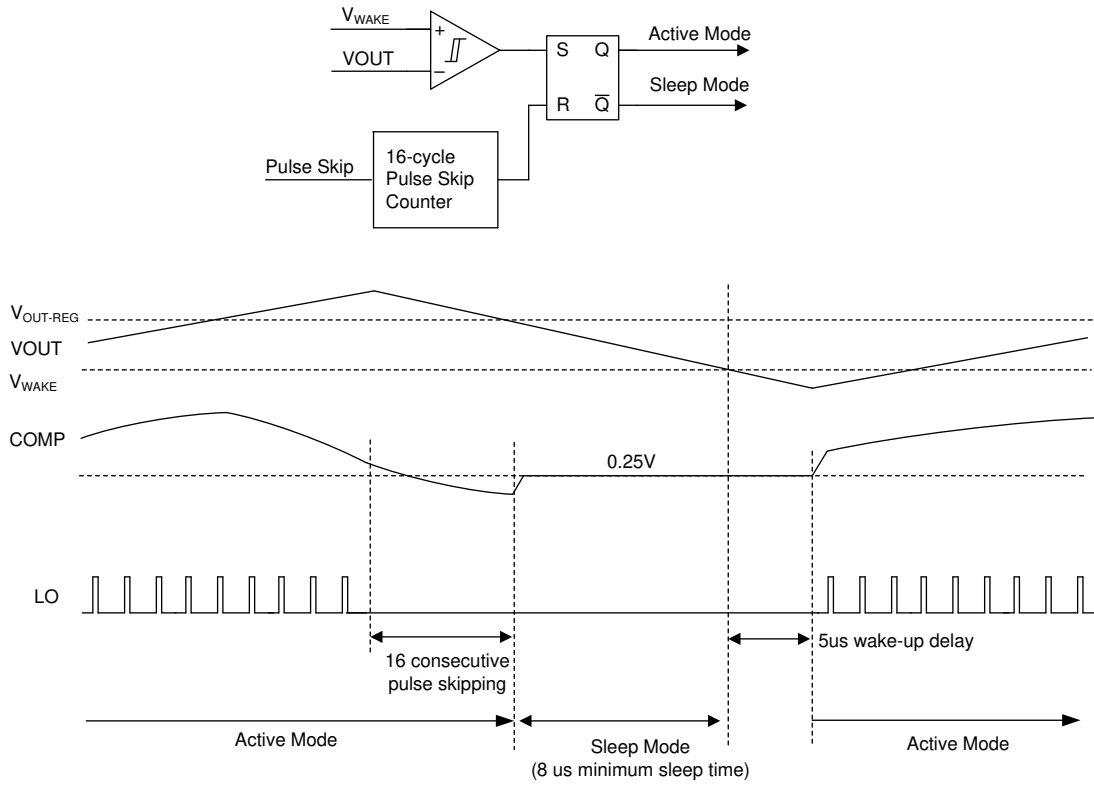
During soft start, the device forces diode emulation while the SS pin voltage is less than 1.5 V. When the SS pin is greater than 1.5 V, the device reduces the zero current detection (ZCD) threshold down to -145 mV. The peak-to-peak inductor current must satisfy 方程式 13 for a proper FPWM operation at no load.

$$\frac{I_{PP} \times R_{DS(on)}}{2} < 145\text{mV} \quad (13)$$

#### 9.4.2.4 Skip Mode

When skip mode is selected as the light load switching mode, the device enters sleep mode when the pulse skip counter detects 16 consecutive cycles of pulse skipping in the active mode, and re-enters the active mode if V<sub>OUT</sub> falls down below V<sub>WAKE</sub>.

The light load efficiency can be increased by entering sleep mode more frequently and staying in sleep mode longer. In skip mode and when SS is greater than 1.5 V, the device works in the diode emulation, but the minimum peak current is limited to 10 mV/R<sub>S</sub> once the low-side driver turns on. By limiting the minimum peak current, the boost converter is able to supply more current than what is required when switching, and enters sleep mode more frequently and stays longer in the sleep mode.



**图 9-24. Skip Mode Operation**

When skip mode is selected as the light load switching mode,  $L_M$  should be selected for the peak inductor to reach the 10m-V minimum peak current limit before  $LO$  turns off by  $D_{MAX}$  at the minimum  $V_{SUPPLY}$ .





## 10.2.2 Detailed Design Procedure

Use the [LM5152-Q1 Quick Start Calculator](#) or [LM51521-Q1 Quick Start Calculator](#) to expedite the process of designing a regulator for a given application.

Refer to the [LM5152EVM-BST User's Guide](#) for recommended components and typical application curves.

### 10.2.2.1 Application Ideas

For applications requiring the lowest cost with minimum conduction loss, inductor DC resistance (DCR) can be used to sense the inductor current rather than using a sense resistor.  $R_{DCRC}$  and  $C_{DCRC}$  must meet [方程式 14](#) to match a time constant.

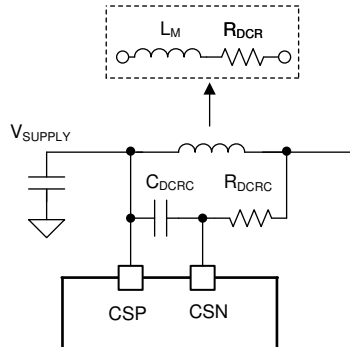


图 10-2. DCR Current Sensing

$$\frac{L_M}{R_{DCR}} = R_{DCRC} \times C_{DCRC} \quad (14)$$

Add a diode from STATUS to DITHER if the clock dithering is required in active mode and the bypass operation is required in deep sleep mode.

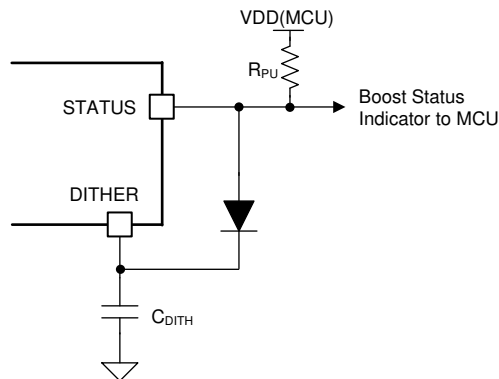


图 10-3. Enable Both Clock Dithering and Bypass Operation

### 10.2.3 Application Curves

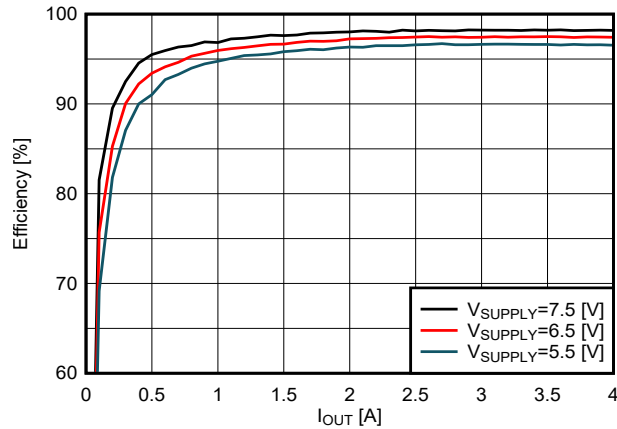


图 10-4. Efficiency vs.  $I_{OUT}$ ,  $V_{OUT} = 8.5\text{ V}$  (FPWM)

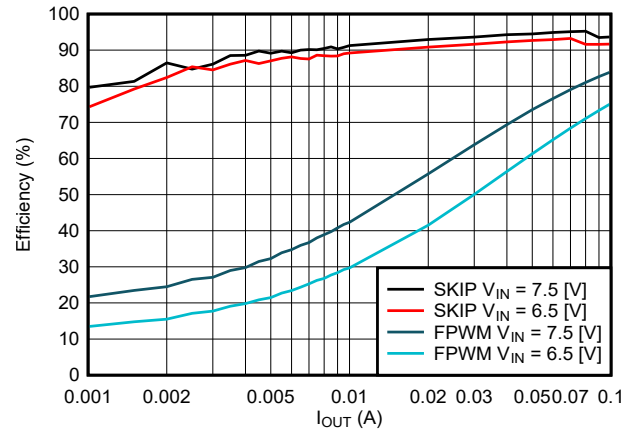


图 10-5. Efficiency vs.  $I_{OUT}$ ,  $V_{OUT} = 8.5\text{-V}$  Light Load

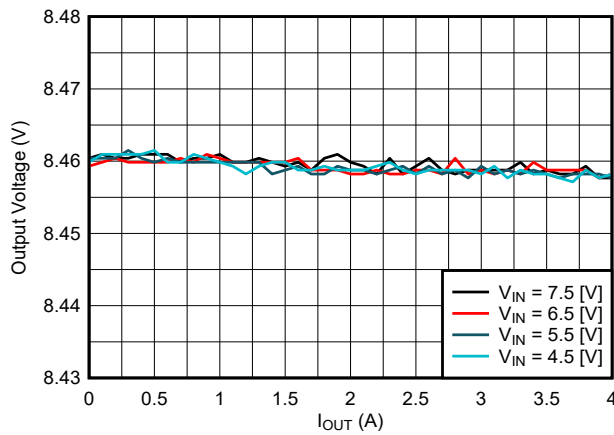


图 10-6. 8.5-V Load Regulation

### 10.3 System Example

Use the LM5152-Q1 in automotive pre-boost applications. The device can turn on the high-side switch 100% when car battery voltage is in normal range.

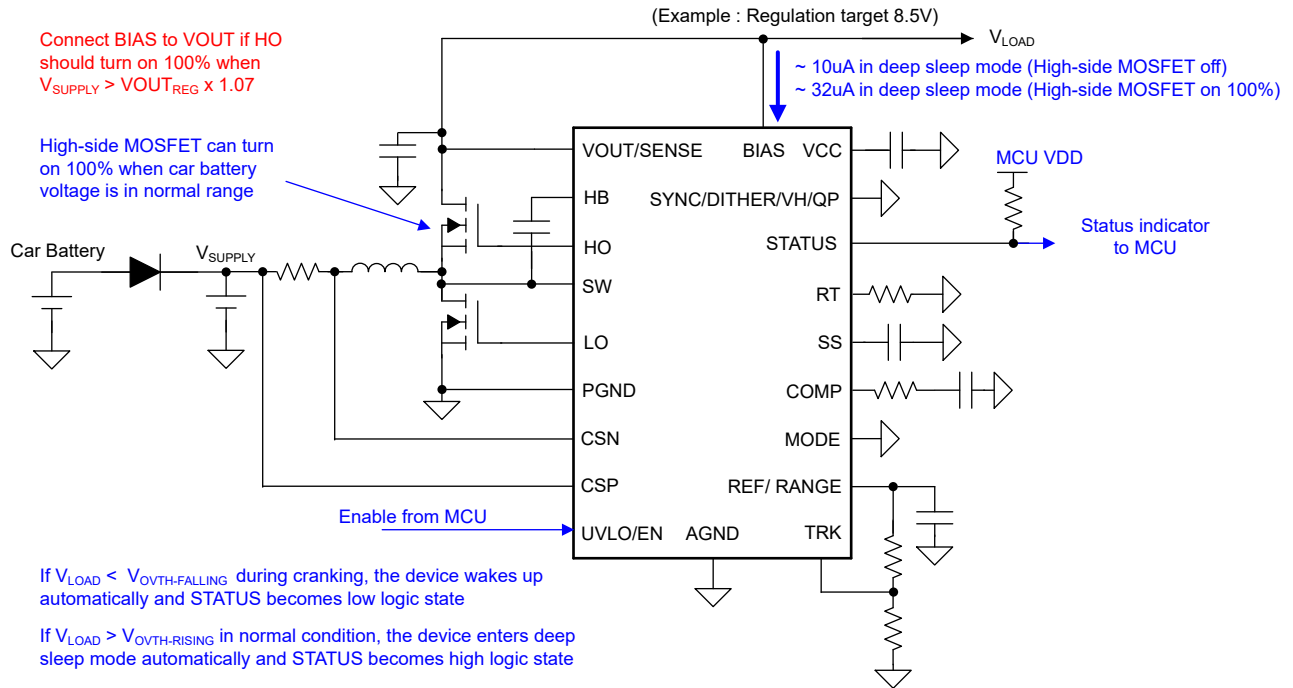


图 10-7. LM5152-Q1 in Automotive Pre-boost Application

Use the LM51521-Q1 in emergency call or backup battery booster application. The LM51521-Q1 turns off the high-side switch when car battery voltage is in normal range.

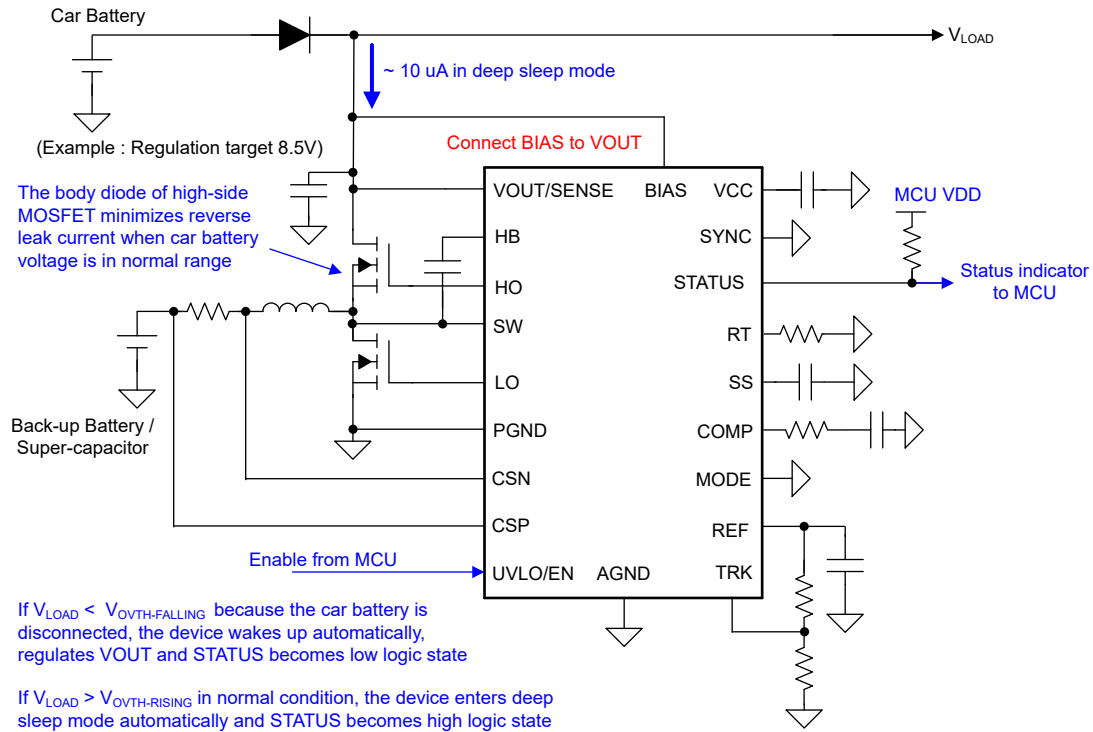


图 10-8. LM51521 in Emergency Call/Backup Battery Booster Application

To configure non-synchronous boost converter, connect SW to PGND, and connect HB to VCC.

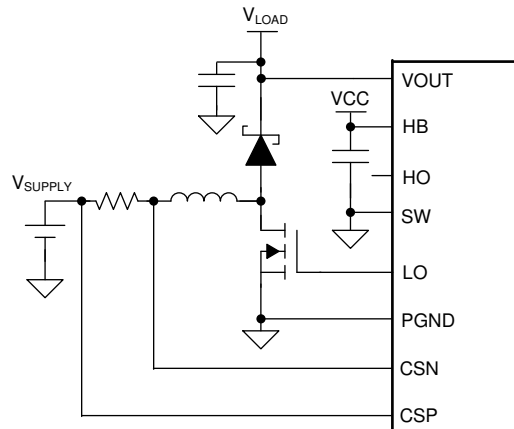


图 10-9. Non-Synchronous Boost Configuration

## 11 Power Supply Recommendations

The device is designed to operate from a power supply or a battery that has a voltage range is from 0.8 V to 42 V. The input power supply must be able to supply the maximum boost supply voltage and handle the maximum input current at 0.8 V. The impedance of the power supply and battery including cables must be low enough that an input current transient does not cause an excessive drop. Additional input ceramic capacitors can be required at the supply input of the converter.

## 12 Layout

### 12.1 Layout Guidelines

The performance of switching converters heavily depends on the quality of the PCB layout. The following guidelines will help users design a PCB with the best power conversion performance, thermal performance, and minimize generation of unwanted EMI.

- Place  $C_{VCC}$ ,  $C_{BIAS}$ ,  $C_{HB}$ , and  $C_{VOUT}$  as close to the device. Make direct connections to the pins.
- Place  $Q_H$ ,  $Q_L$ , and  $C_{OUT}$ . Make the switching loop ( $C_{OUT}$  to  $Q_H$  to  $Q_L$  to  $C_{OUT}$ ) as small as possible. A small size ceramic capacitor helps to minimize the loop length. Leave a copper area near the drain connection of  $Q_H$  for a thermal dissipation.
- Place  $L_M$ ,  $R_S$ , and  $C_{IN}$ . Make the loop ( $C_{IN}$  to  $R_S$  to  $L_M$  to  $C_{IN}$ ) as small as possible. A small size ceramic capacitor helps to minimize the loop length.
- Connect  $R_S$  to CSP-CSN. The CSP-CSN traces must be routed in parallel and surrounded by ground.
- Connect VOUT, HO, and SW. These traces must be routed in parallel using a short, low inductance path. VOUT must be directly connected the drain connection of  $Q_H$ . SW must be directly connected to the source connection of  $Q_H$ .
- Connect LO and PGND. The LO-PGND traces must be routed in parallel using a short, low inductance path. PGND must be directly connected the source connection of  $Q_L$ .
- Place  $R_{COMP}$ ,  $C_{COMP}$ ,  $C_{SS}$ ,  $C_{VREF}$ ,  $R_{VREF}$ ,  $R_{VREFB}$ ,  $R_T$ , and  $R_{UVLOB}$  as close to the device, and connect to a common analog ground plane.
- Connect the power ground plane (the source connection of the  $Q_L$ ) to EP through PGND. Connect the common analog ground plane to EP through AGND. PGND and AGND must be connected underneath the device.
- Add several vias under EP to help conduct heat away from the device. Connect the vias to a large analog ground plane on the bottom layer.
- Do not connect  $C_{OUT}$  and  $C_{IN}$  grounds underneath the device and through the large analog ground plane that is connected to EP.

## 12.2 Layout Example

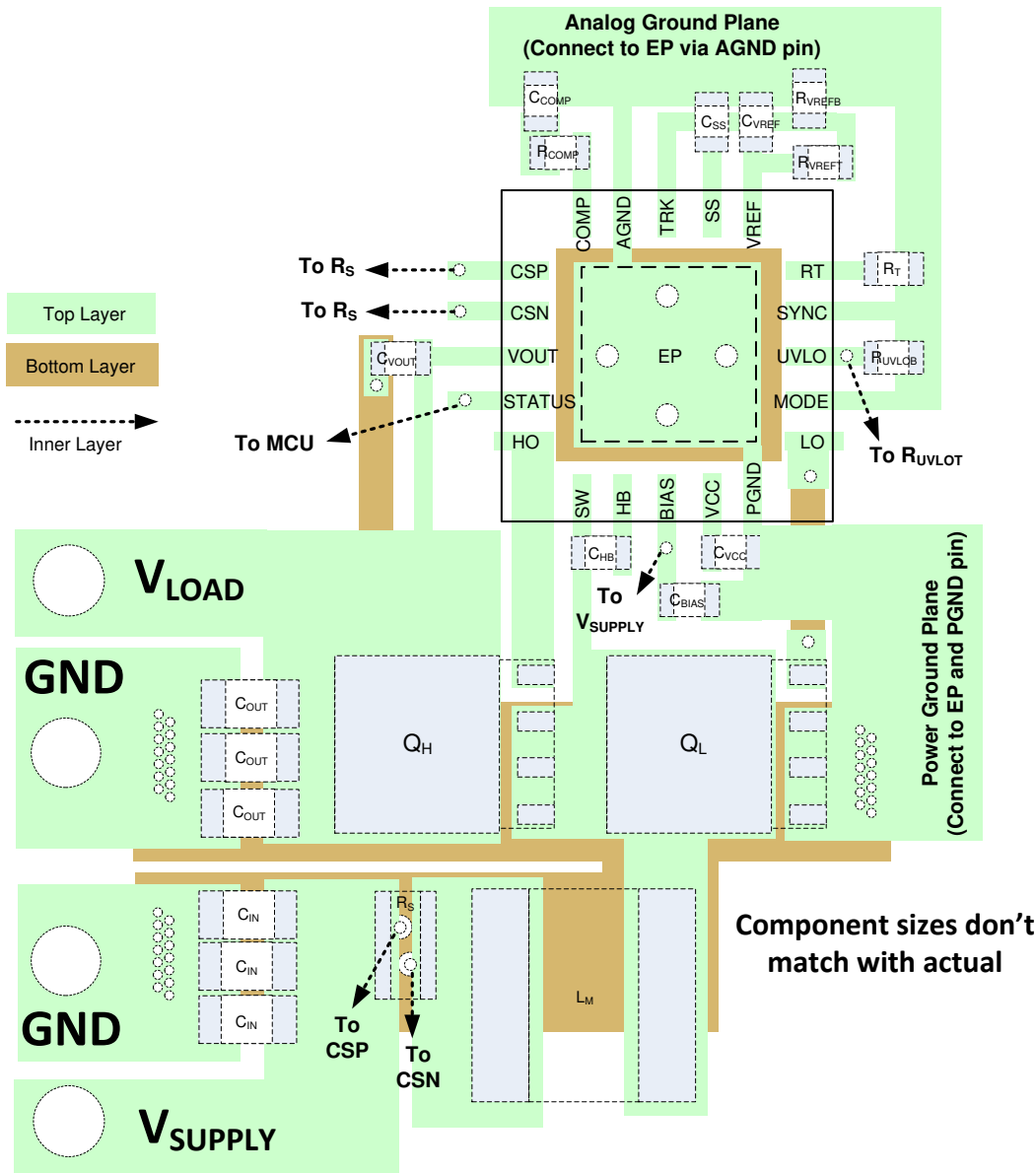


图 12-1. PCB Layout Example

## 13 Device and Documentation Support

### 13.1 Device Support

#### 13.1.1 第三方产品免责声明

TI 发布的与第三方产品或服务有关的信息，不能构成与此类产品或服务或保修的适用性有关的认可，不能构成此类产品或服务单独或与任何 TI 产品或服务一起的表示或认可。

#### 13.2 接收文档更新通知

要接收文档更新通知，请导航至 [ti.com](https://www.ti.com) 上的器件产品文件夹。点击 [订阅更新](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

#### 13.3 支持资源

TI E2E™ [支持论坛](#) 是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [《使用条款》](#)。

#### 13.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

所有商标均为其各自所有者的财产。

#### 13.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

#### 13.6 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

## 14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM51521QRGRRQ1	ACTIVE	VQFN	RGR	20	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 150	L51521	<a href="#">Samples</a>
LM5152QRGRRQ1	ACTIVE	VQFN	RGR	20	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 150	LM5152	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.





**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM51521QRGRRQ1	VQFN	RGR	20	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q2
LM5152QRGRRQ1	VQFN	RGR	20	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q2

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM51521QRGRRQ1	VQFN	RGR	20	3000	367.0	367.0	35.0
LM5152QRGRRQ1	VQFN	RGR	20	3000	367.0	367.0	35.0

## GENERIC PACKAGE VIEW

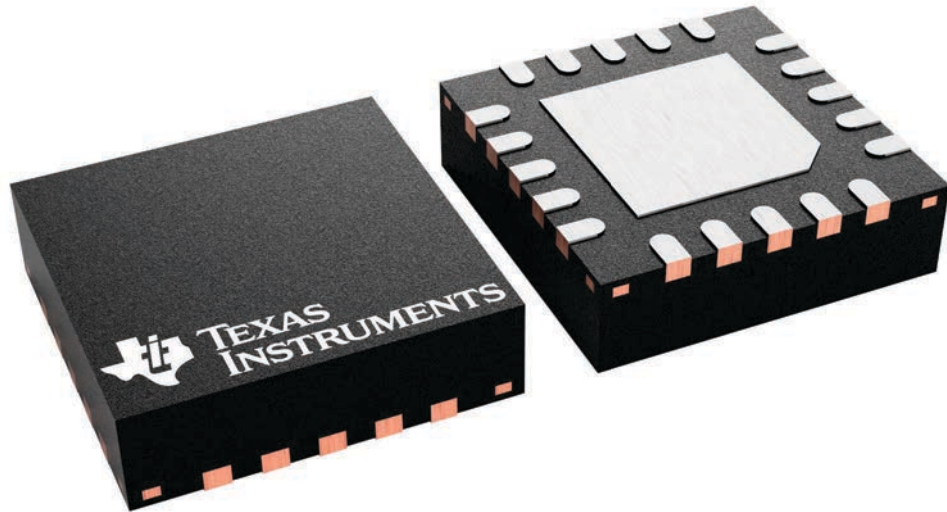
**RGR 20**

**VQFN - 1 mm max height**

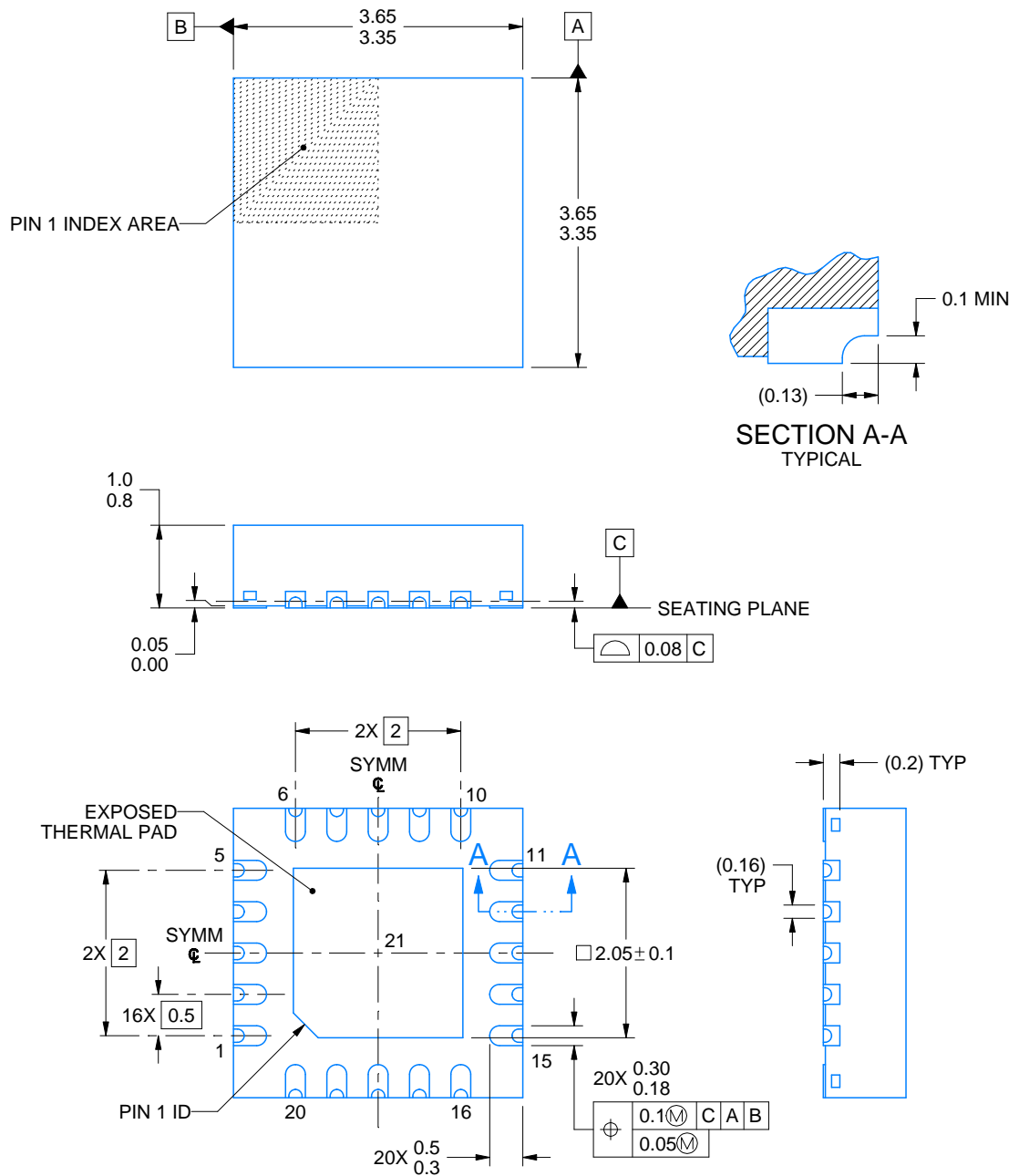
3.5 x 3.5, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4228482/A



4225699/B 05/2020

NOTES:

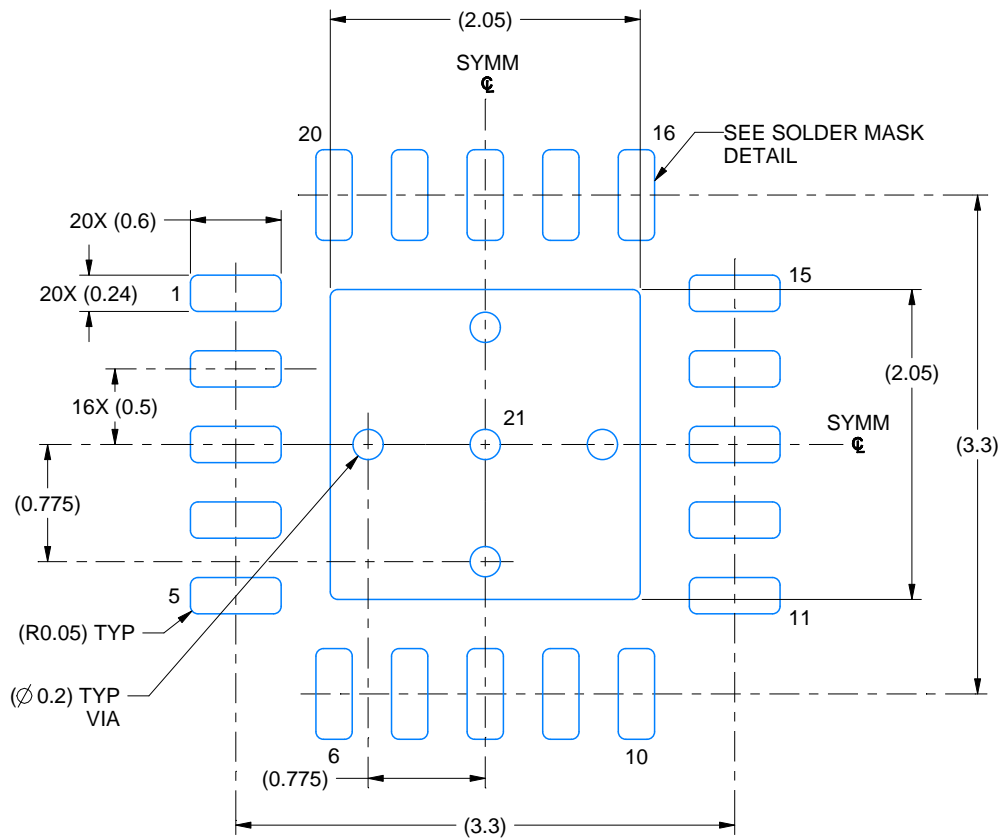
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

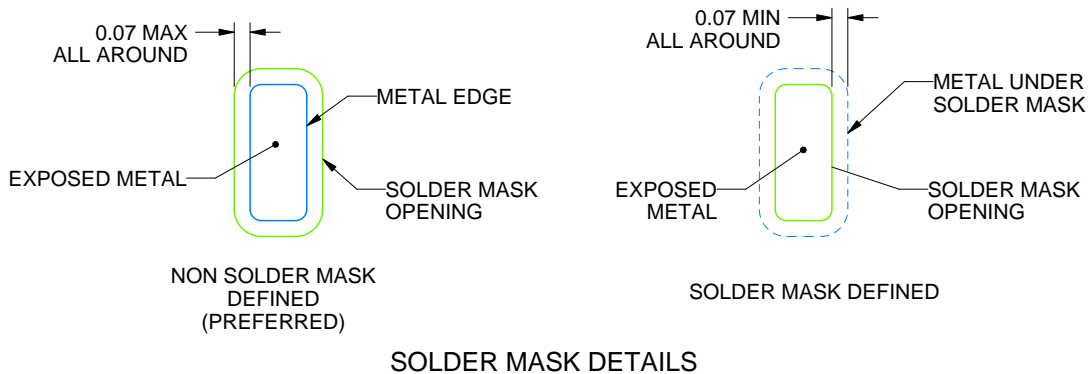
RGR0020C

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 20X



SOLDER MASK DETAILS

4225699/B 05/2020

NOTES: (continued)

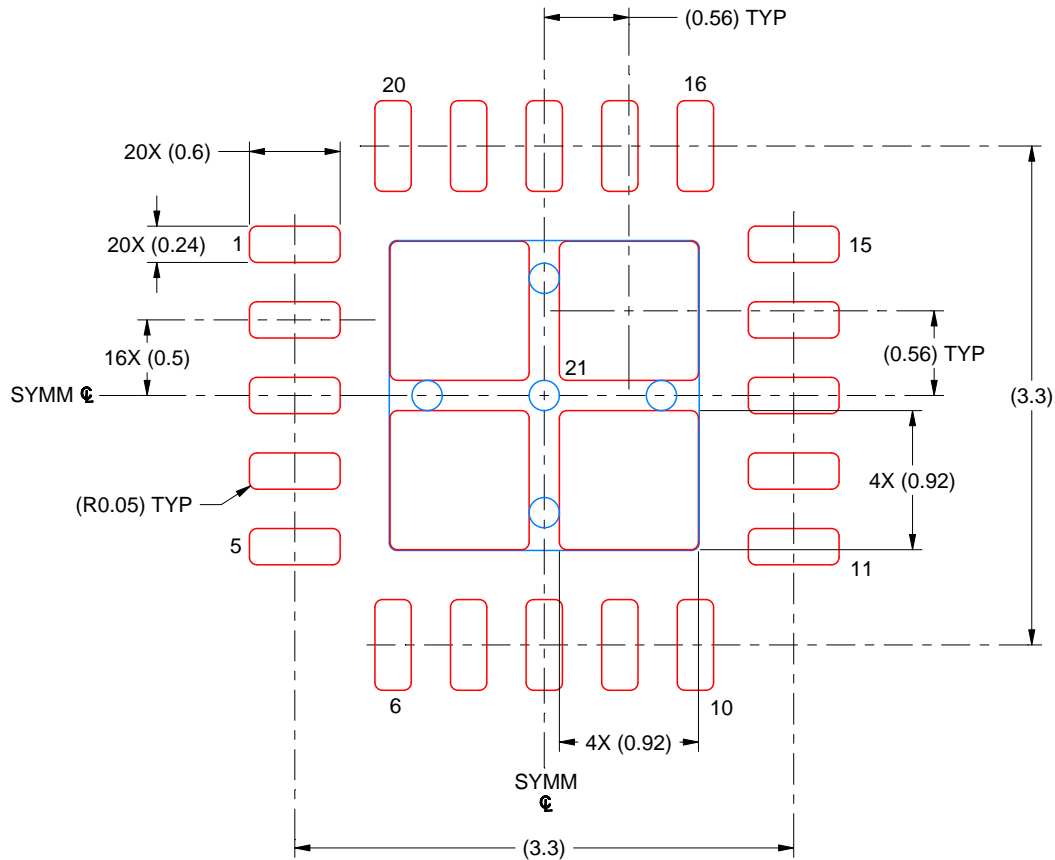
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

RGR0020C

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.125 MM THICK STENCIL  
SCALE: 20X

EXPOSED PAD 21  
81% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

4225699/B 05/2020

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

## 重要声明和免责声明

TI“按原样”提供技术和可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证没有瑕疵且不做任何明示或暗示的担保，包括但不限于对适销性、某特定用途方面的适用性或不侵犯任何第三方知识产权的暗示担保。

这些资源可供使用 TI 产品进行设计的熟练开发人员使用。您将自行承担以下全部责任：(1) 针对您的应用选择合适的 TI 产品，(2) 设计、验证并测试您的应用，(3) 确保您的应用满足相应标准以及任何其他功能安全、信息安全、监管或其他要求。

这些资源如有变更，恕不另行通知。TI 授权您仅可将这些资源用于研发本资源所述的 TI 产品的应用。严禁对这些资源进行其他复制或展示。您无权使用任何其他 TI 知识产权或任何第三方知识产权。您应全额赔偿因在这些资源的使用中对 TI 及其代表造成的任何索赔、损害、成本、损失和债务，TI 对此概不负责。

TI 提供的产品受 [TI 的销售条款](#) 或 [ti.com](#) 上其他适用条款/TI 产品随附的其他适用条款的约束。TI 提供这些资源并不会扩展或以其他方式更改 TI 针对 TI 产品发布的适用的担保或担保免责声明。

TI 反对并拒绝您可能提出的任何其他或不同的条款。

邮寄地址：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

Copyright © 2022，德州仪器 (TI) 公司